

ENEE 359a

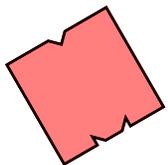
Digital VLSI Design

Course Overview: Transistors to Systems

Prof. Bruce Jacob
blj@eng.umd.edu

Credit where credit is due:

Slides contain original artwork (© Jacob 2004) as well as material taken liberally from Irwin & Vijay's CSE477 slides (PSU), Schmit & Strojwas's 18-322 slides (CMU), Wolf's slides for *Modern VLSI Design*, and/or Rabaey's slides (UCB).

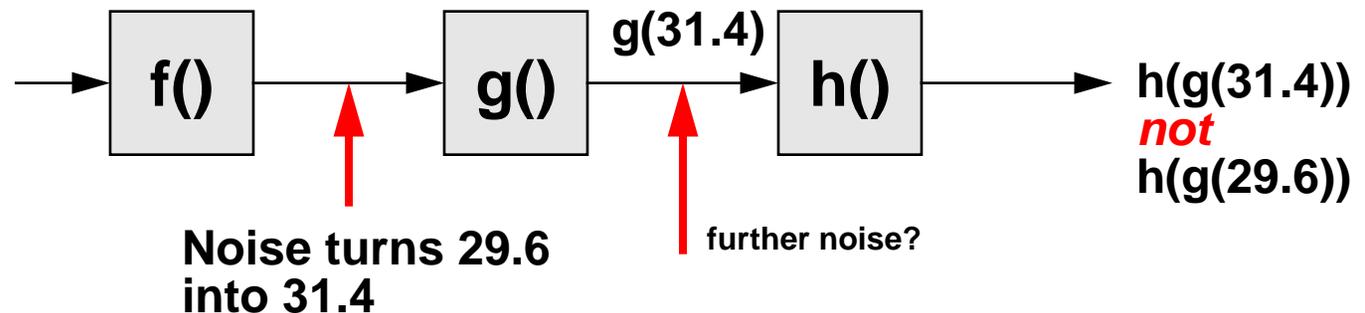


Why Digital?

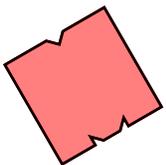
Assume noise in your electronics ...

(lights flicker for no apparent reason,
speakers pop when refrigerator turns on,
cable station comes in fuzzy, etc.)

...and you want to eliminate/reduce problem

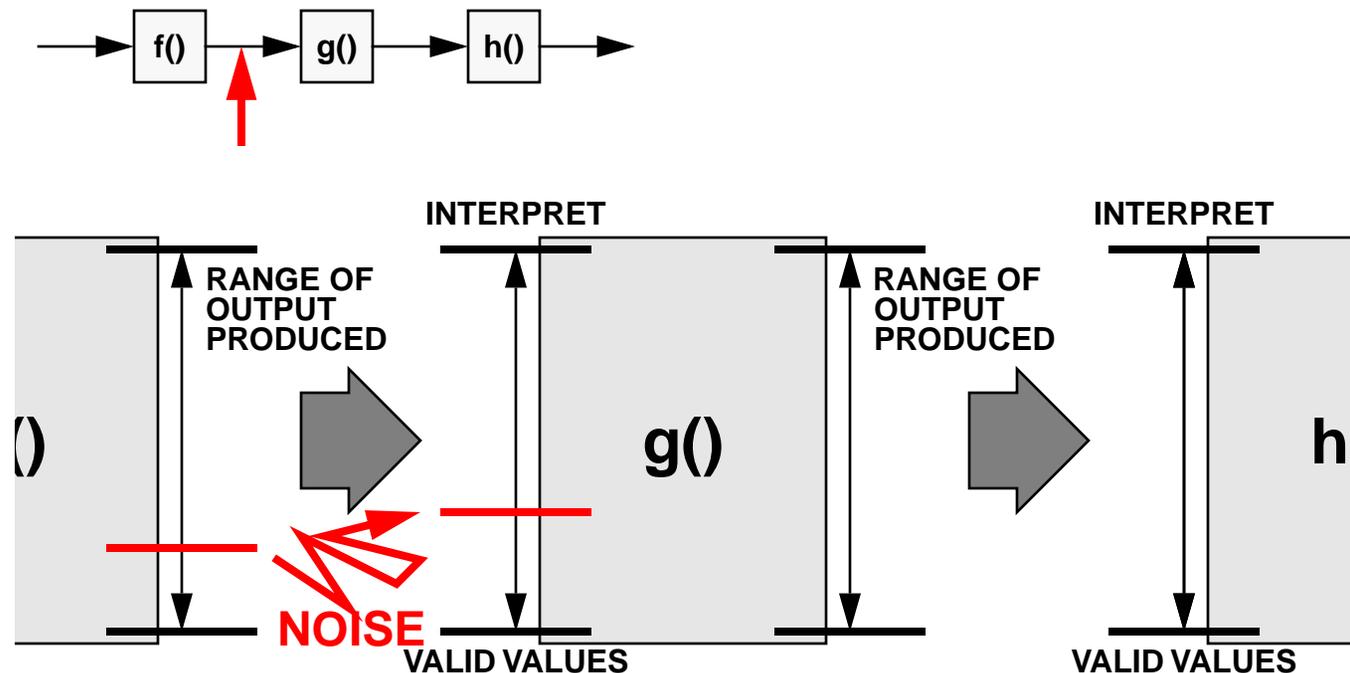


Analog: noise-induced errors **propagate** and **accumulate** (e.g., further noise?); hard to distinguish noisy signal from “true” signal



Why Digital?

How would *YOU* solve the problem?

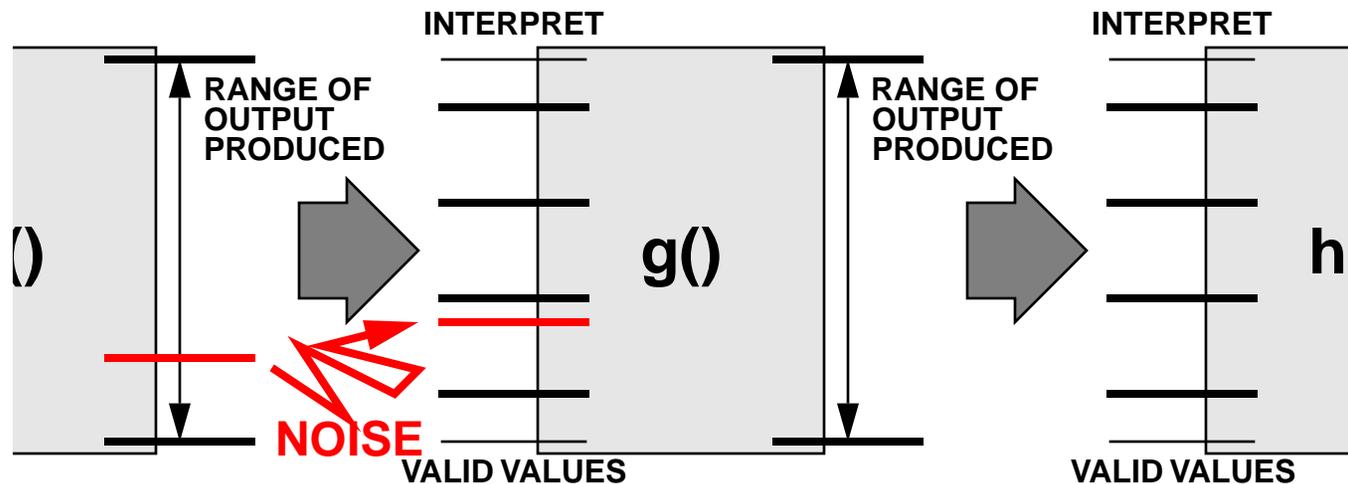
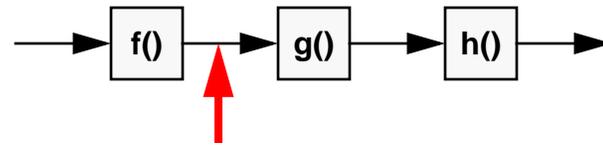


- Problem arises because the entire range of output values is fair game as input
- Thus, it is hard to distinguish corrupted or noisy signal from “true” signal

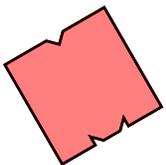


Why Digital?

How would *YOU* solve the problem?

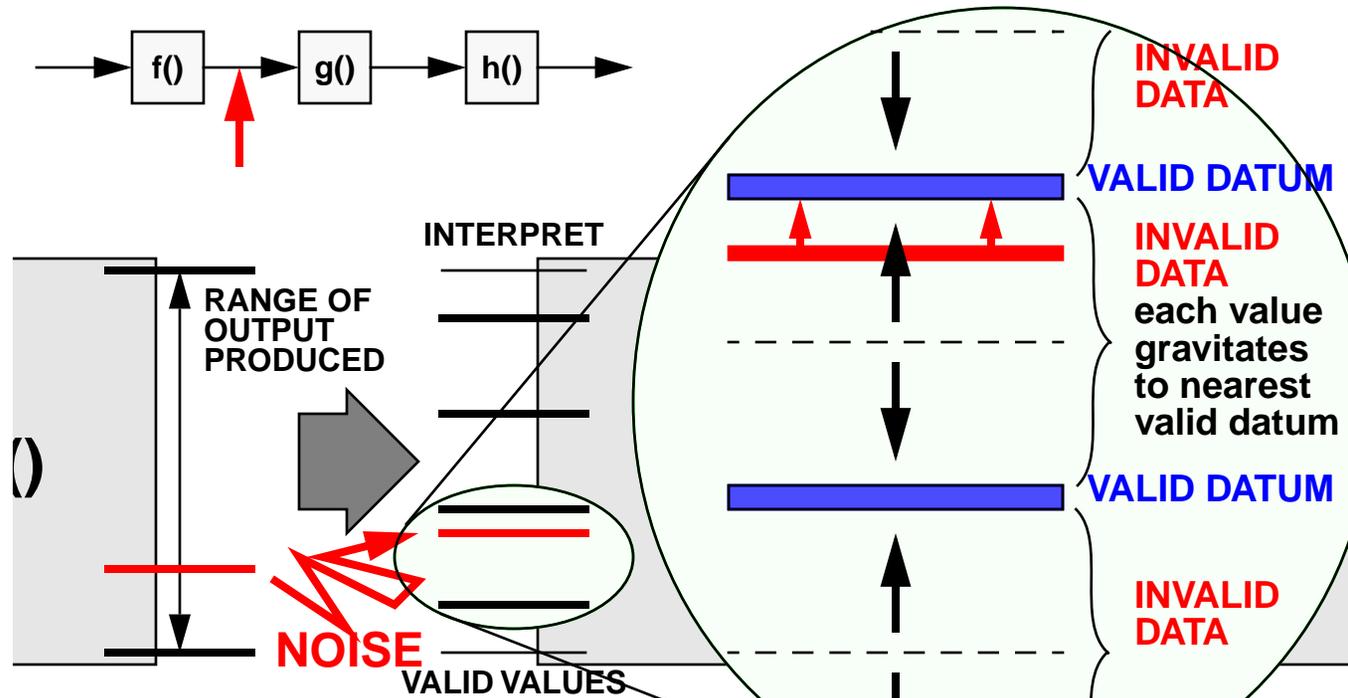


- **ECC-protect all transmissions?**
(can't, literally, but can do an analogy ...)
- **Use a smaller valid-data range so that small errors don't matter**

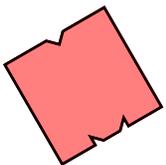


Why Digital?

How would *YOU* solve the problem?

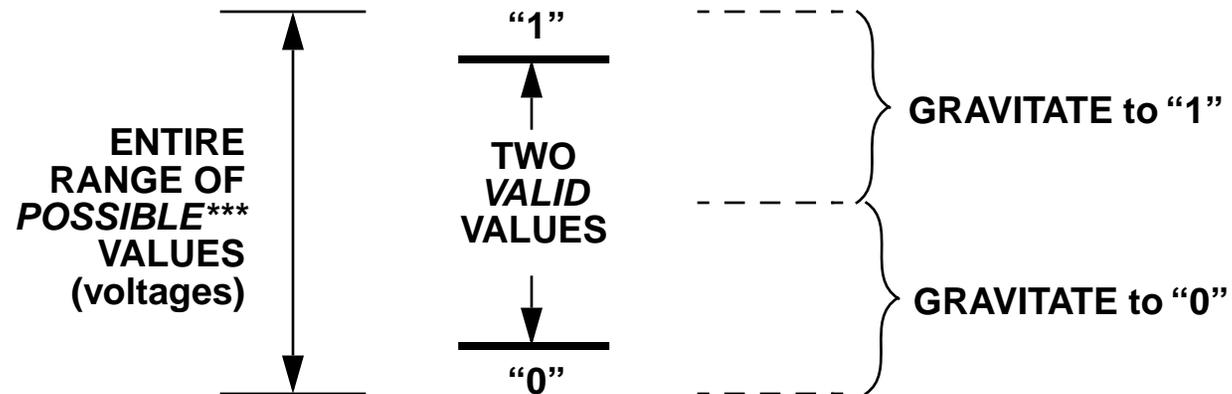


- ECC does this numerically; here, we're talking about interpreting voltage levels
- Relatively straight-forward to do this with various types of amplifiers



Why Digital?

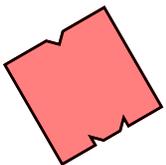
Take this to the extreme:



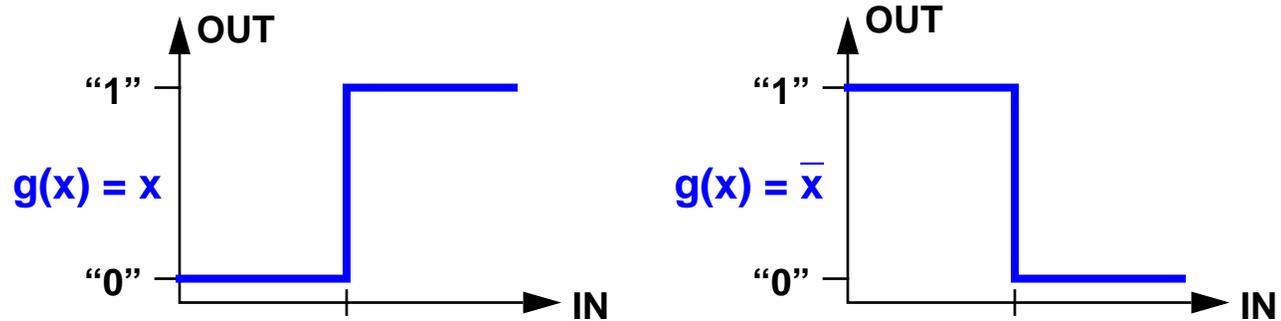
BINARY (two values)

- Very robust in the face of noise
- Well-suited to **BOOLEAN LOGIC**

*** Dramatic oversimplification

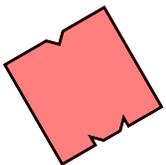
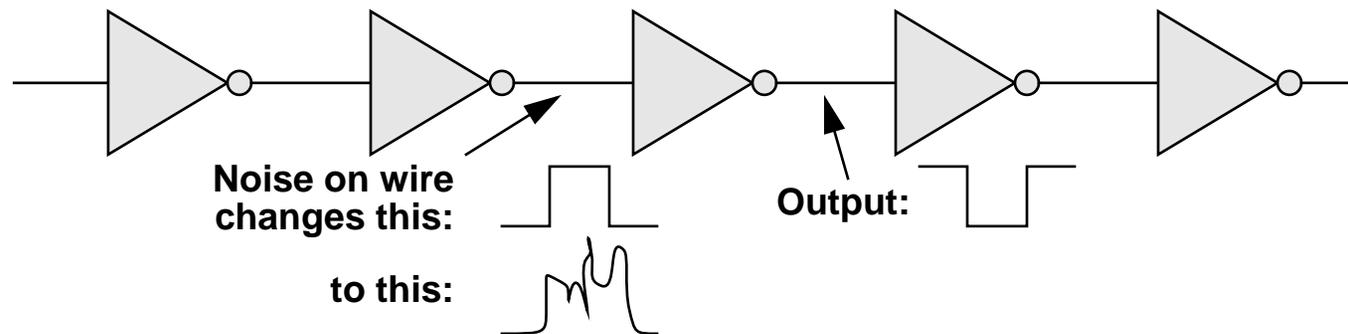


Why Is This Robust?

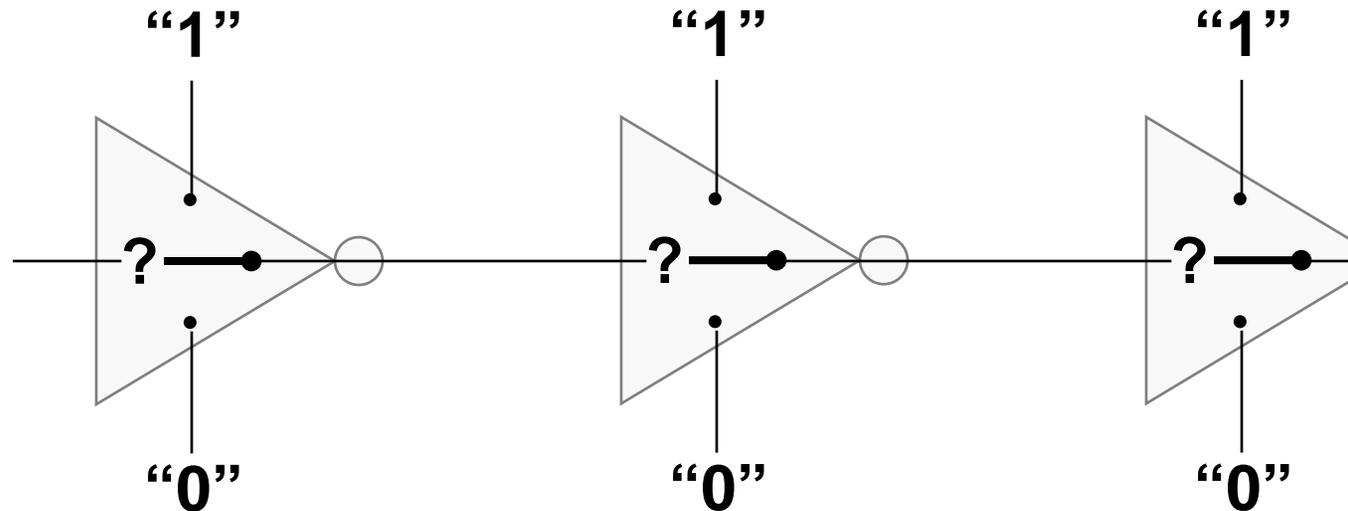


These curves are said to be *regenerative*
Noise neither *propagates* nor *accumulates*

This is exactly what digital logic does,
e.g. chain of inverters:



How Is It Done? (devices)

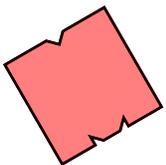


Implementation: Transistors (switches)

Inverter Function:

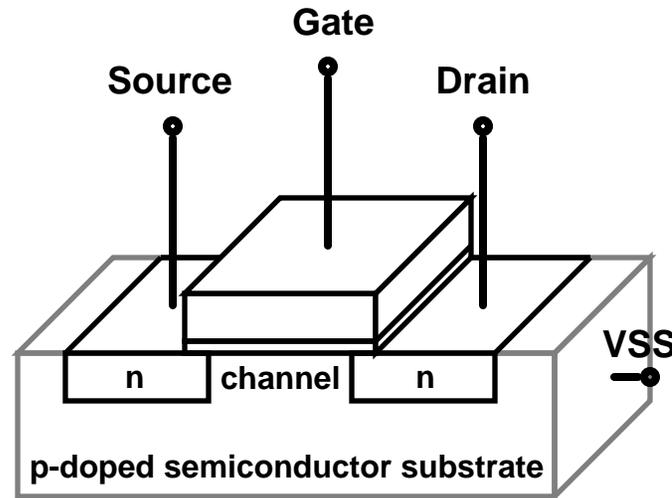
Do I connect my output to "1" or "0"?

Each is effectively a *signal repeater*

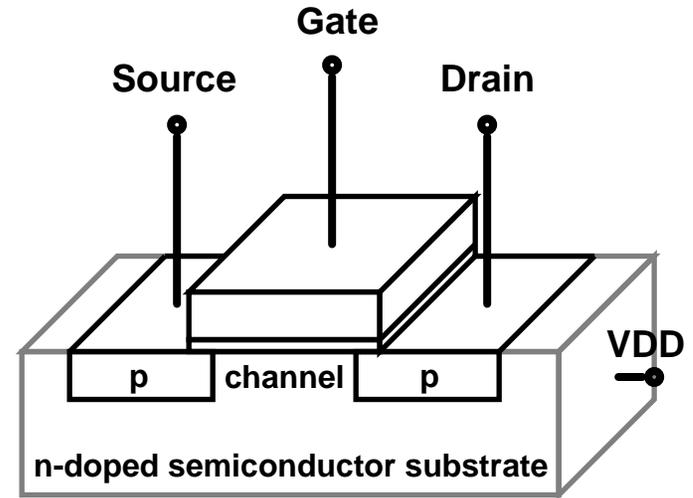


How Is It Done? (devices)

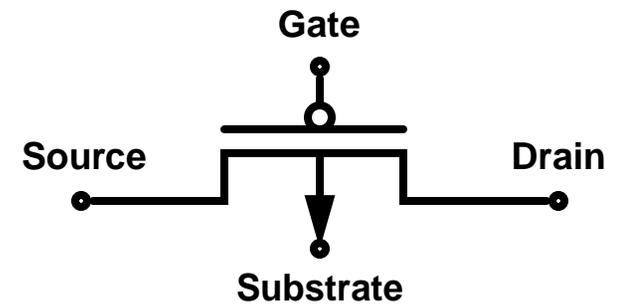
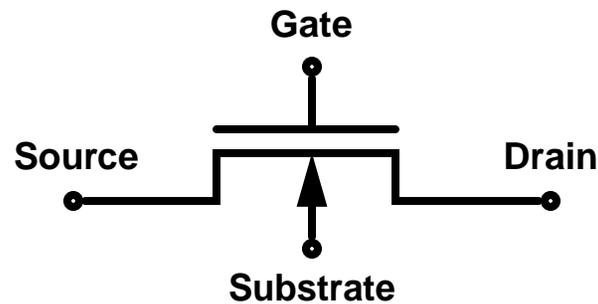
MOS Transistors:



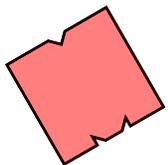
NMOS



PMOS

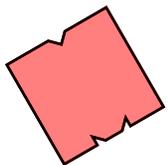
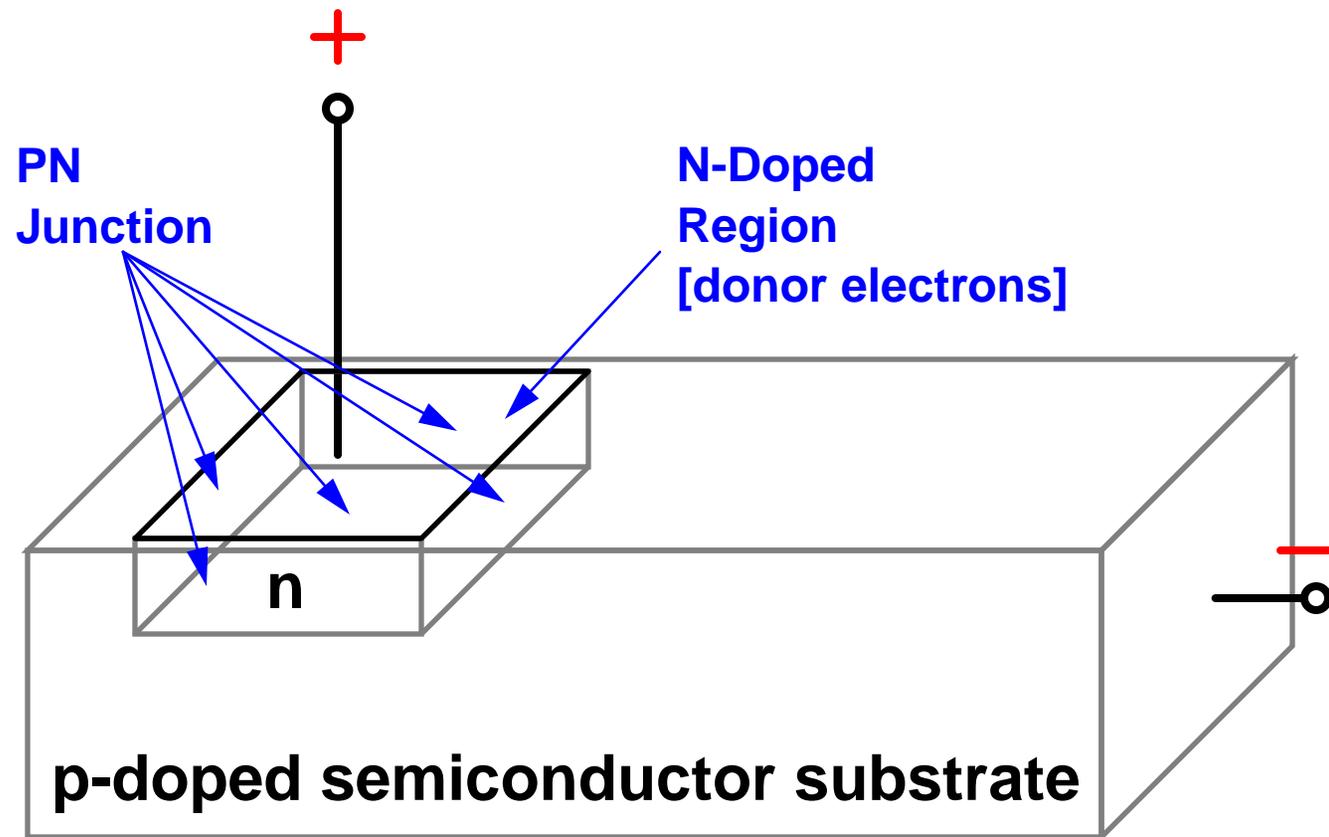


What's a "C" MOS?



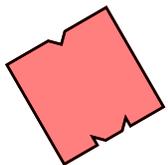
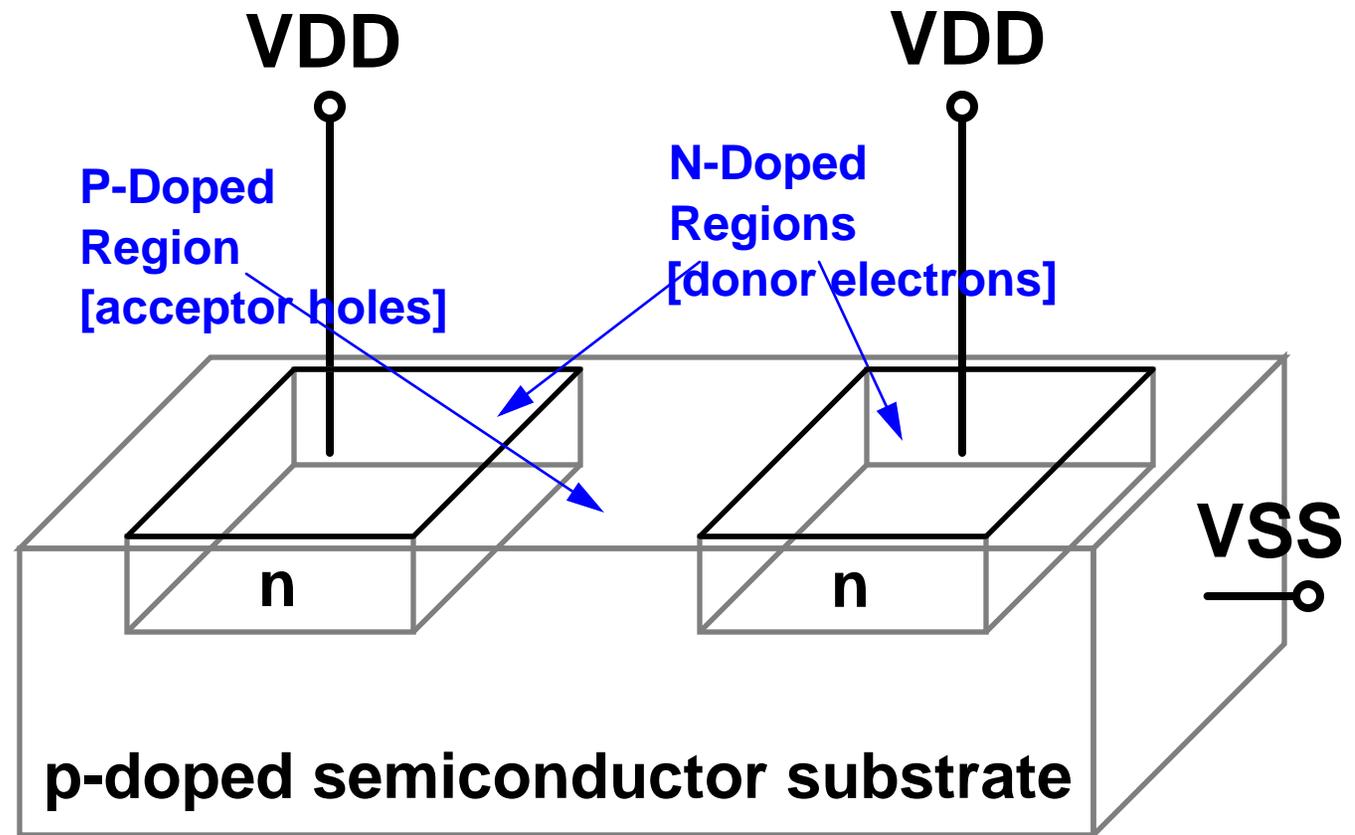
How Is It Done? (devices)

MOS Transistor:



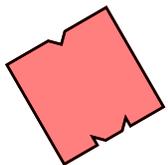
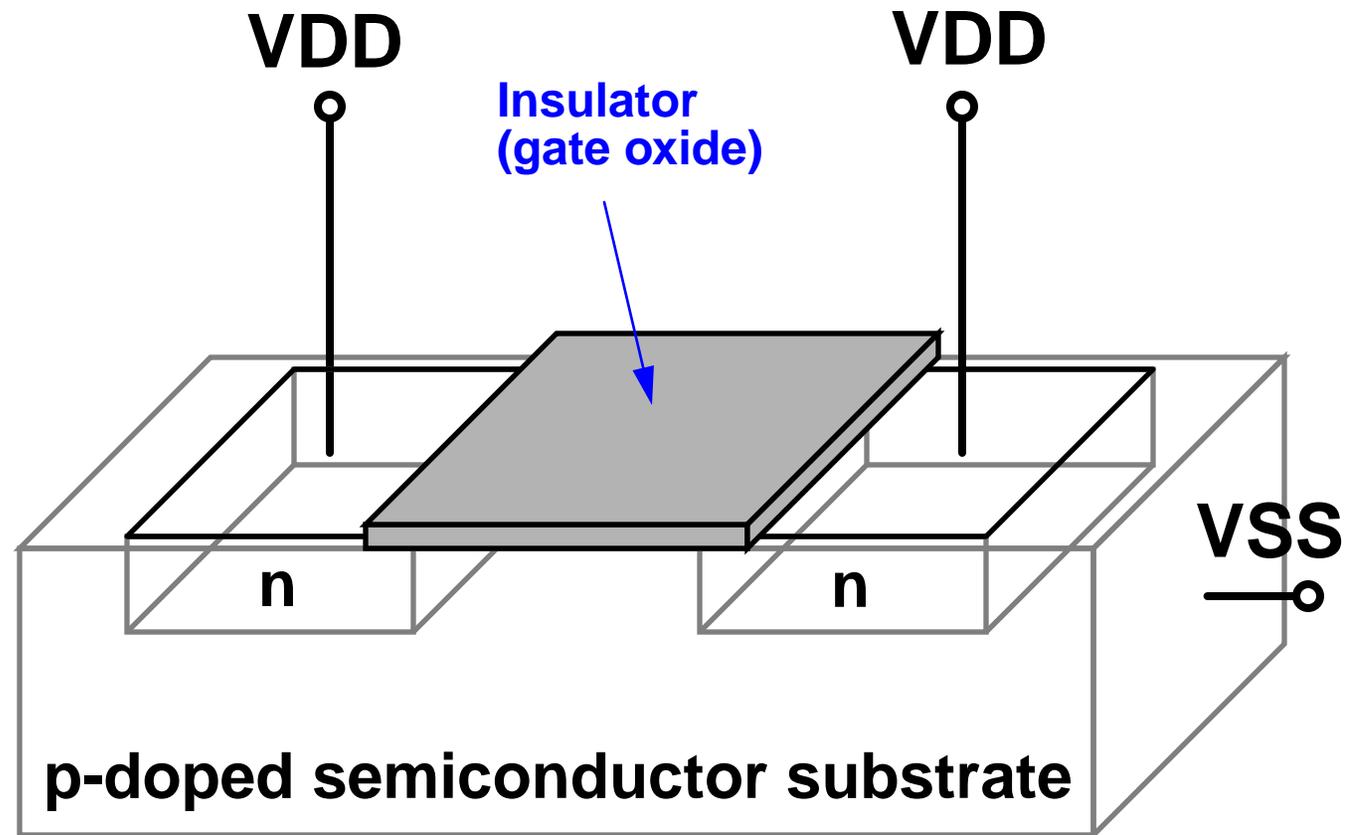
How Is It Done? (devices)

MOS Transistor:



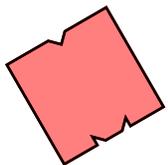
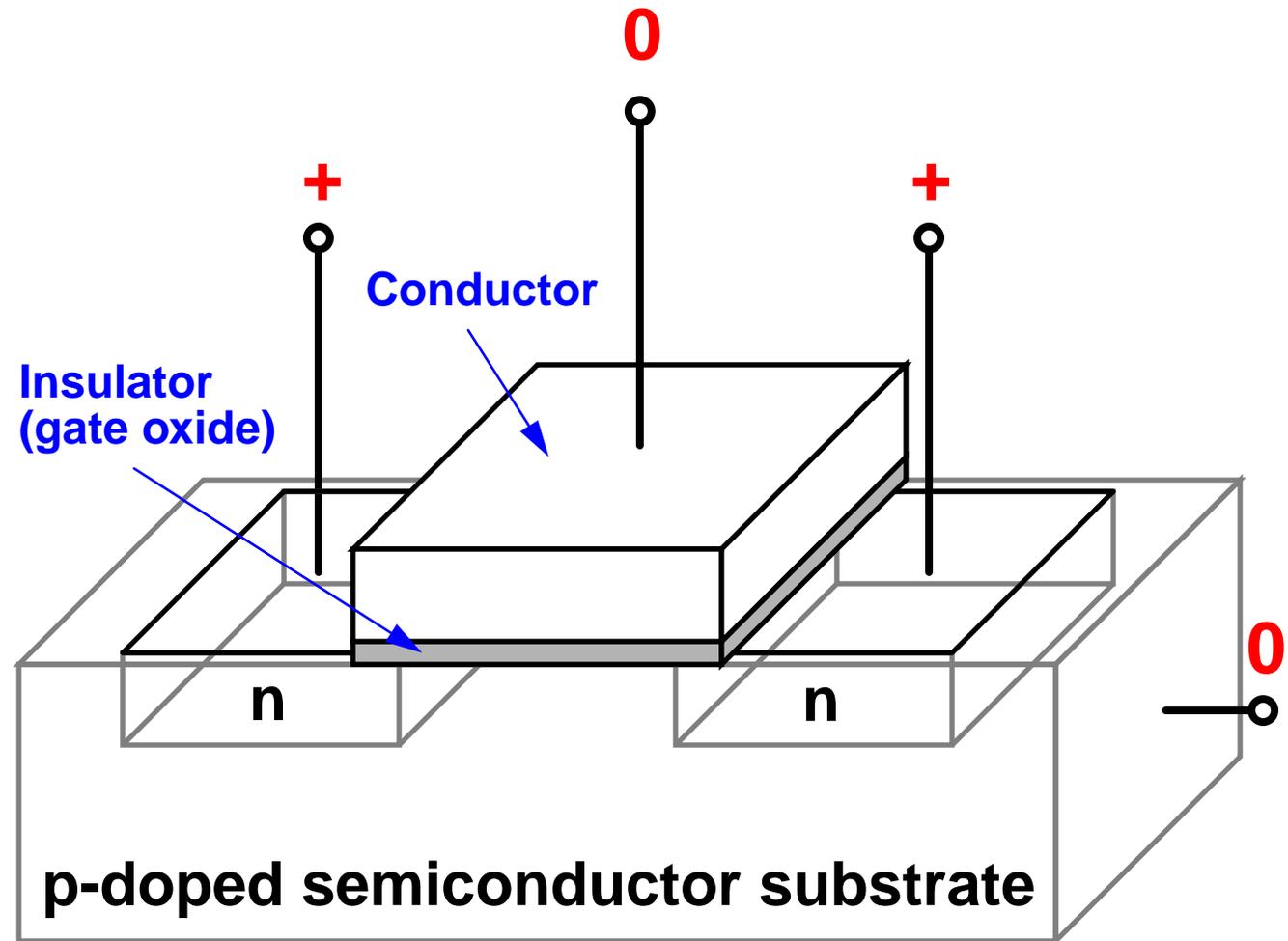
How Is It Done? (devices)

MOS Transistor:



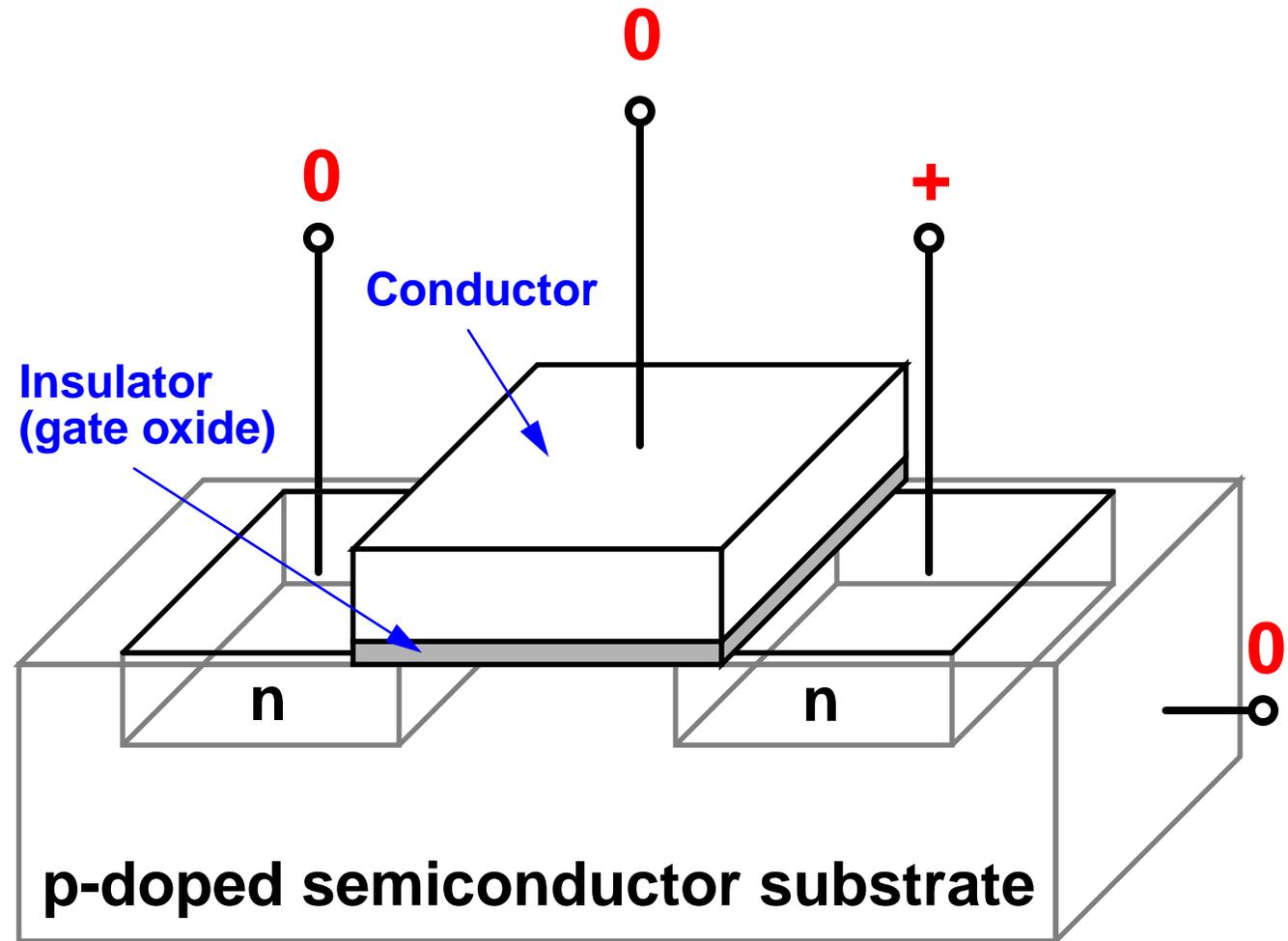
How Is It Done? (devices)

NMOS Transistor with gate:



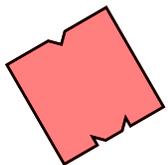
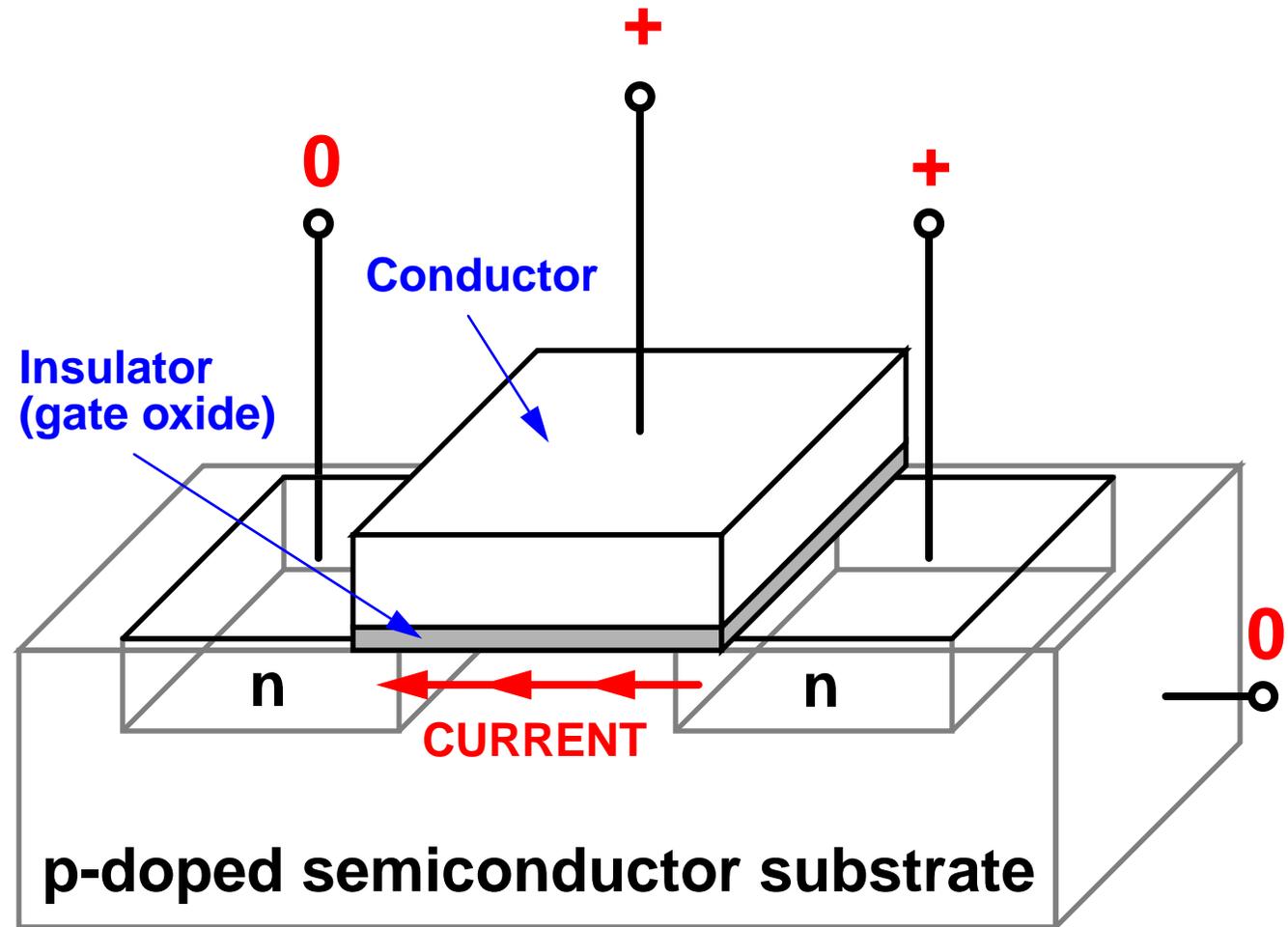
How Is It Done? (devices)

NMOS Transistor with bias voltages:



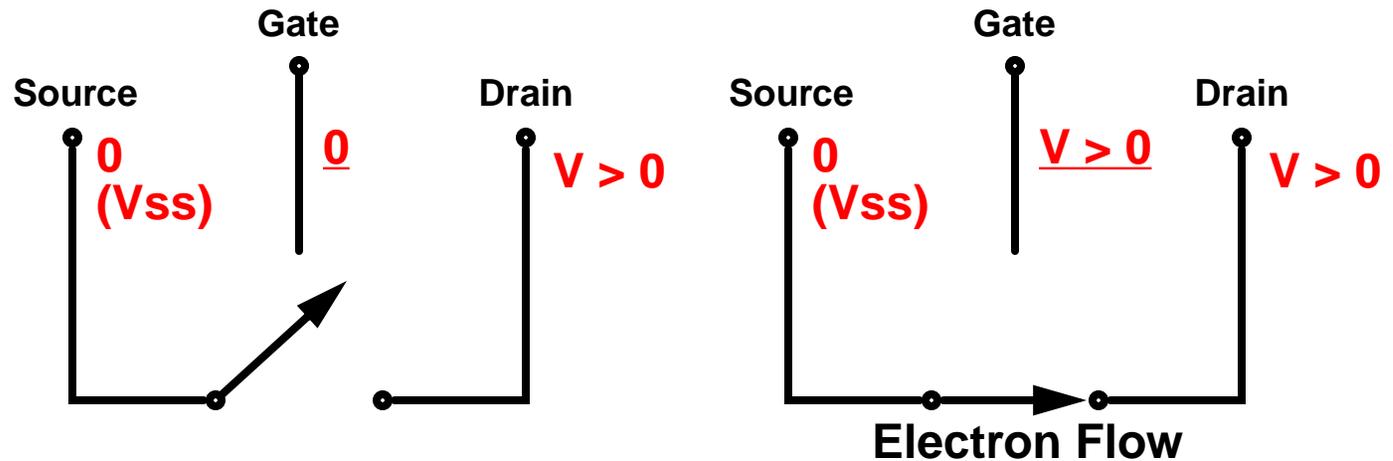
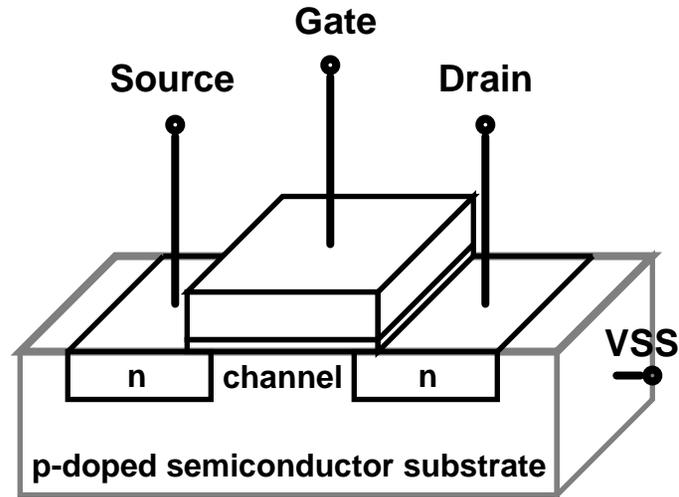
How Is It Done? (devices)

NMOS Transistor with bias voltages:



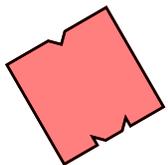
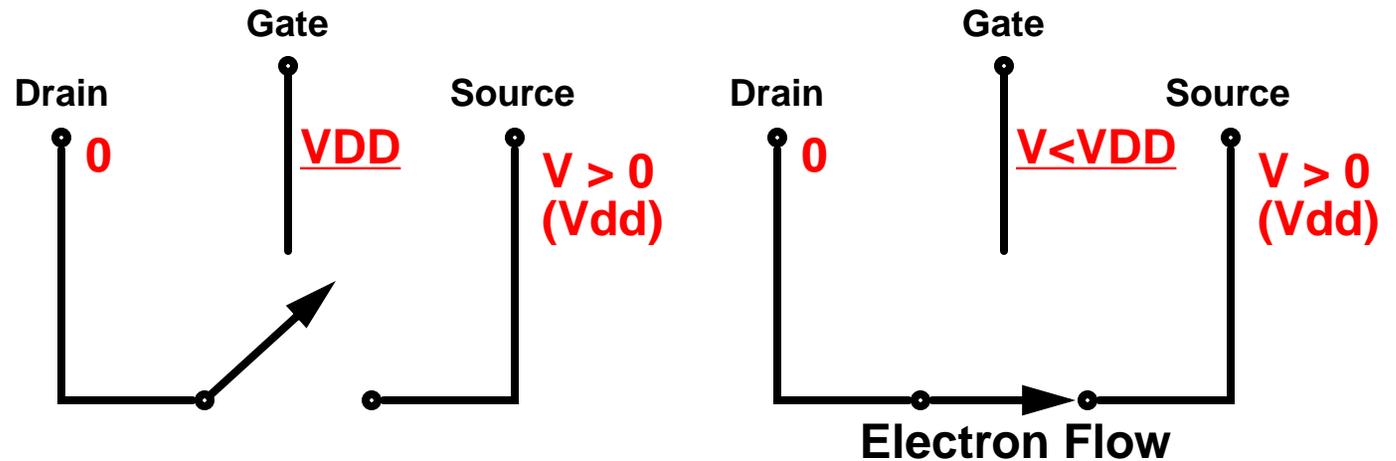
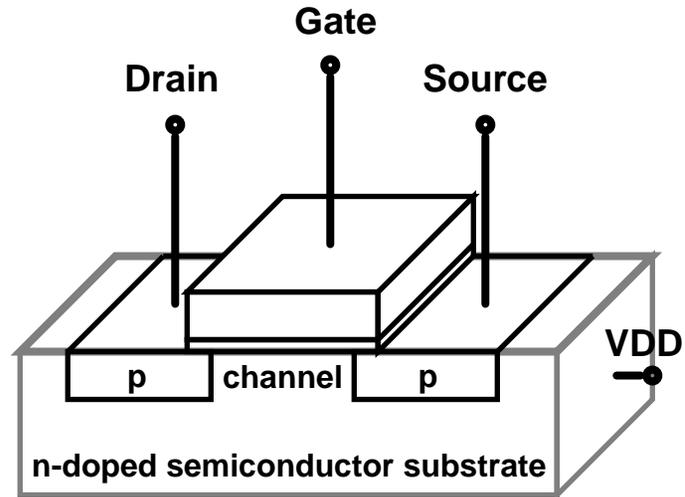
How Is It Done? (devices)

NMOS Transistor with bias voltages:



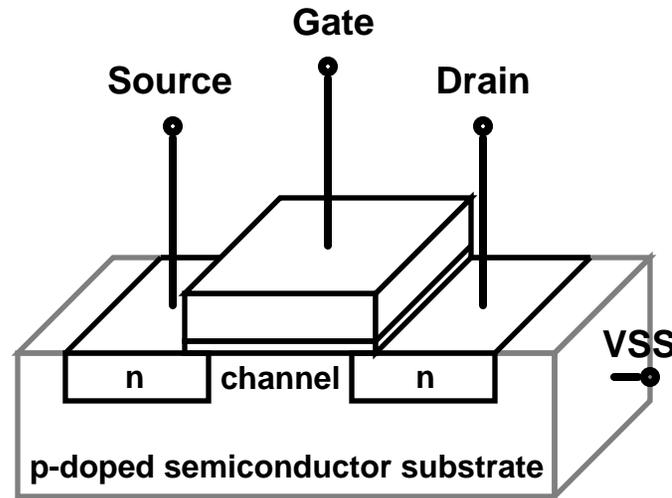
How Is It Done? (devices)

PMOS Transistor with bias voltages:

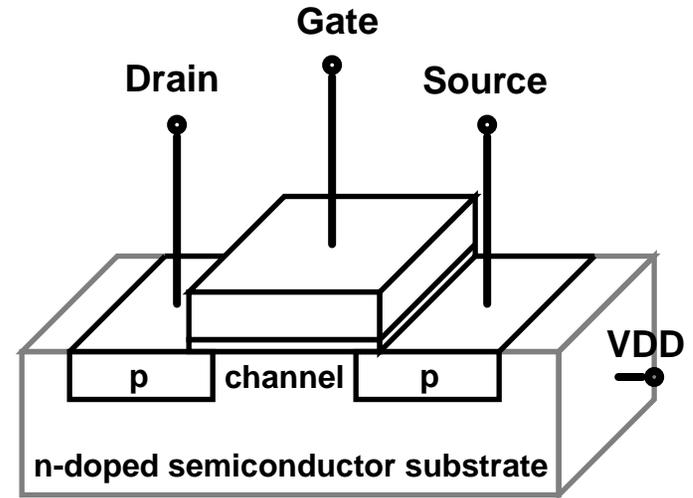


How Is It Done? (devices)

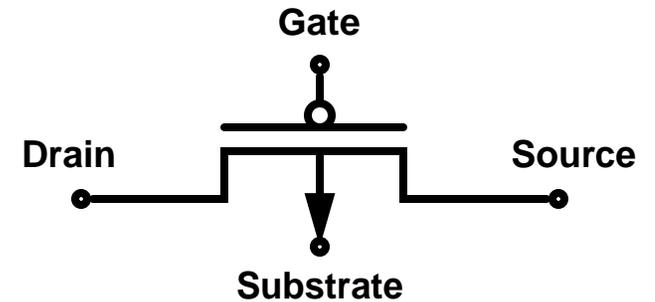
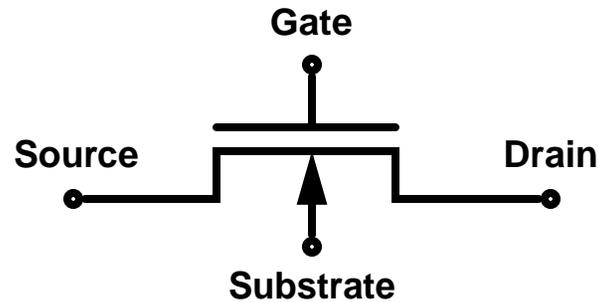
MOS Transistors:



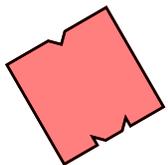
NMOS



PMOS

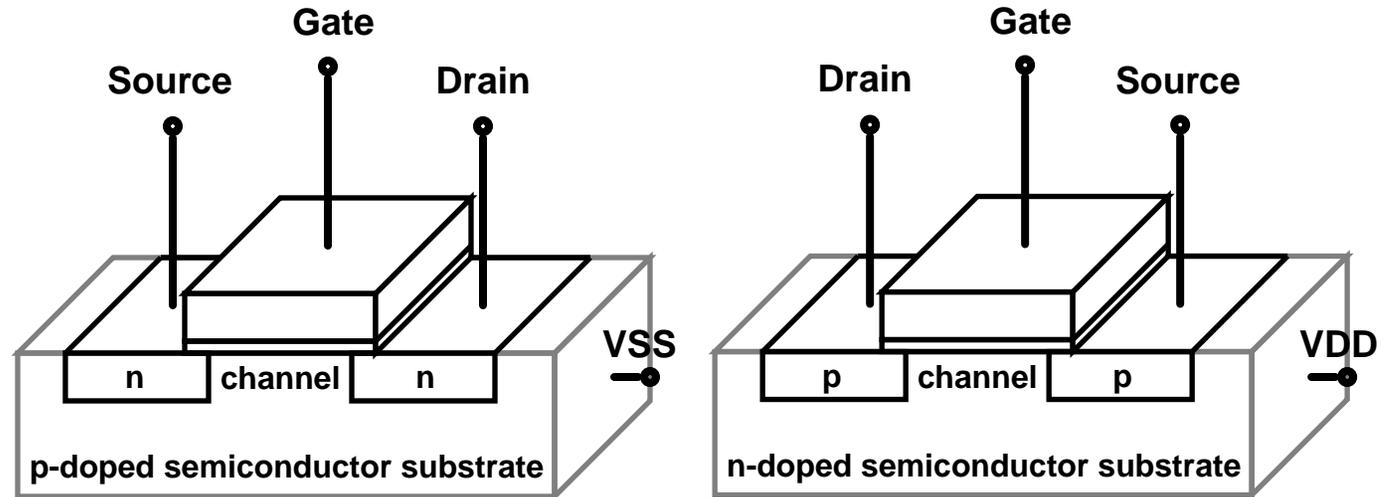


CMOS Inverter = one of each



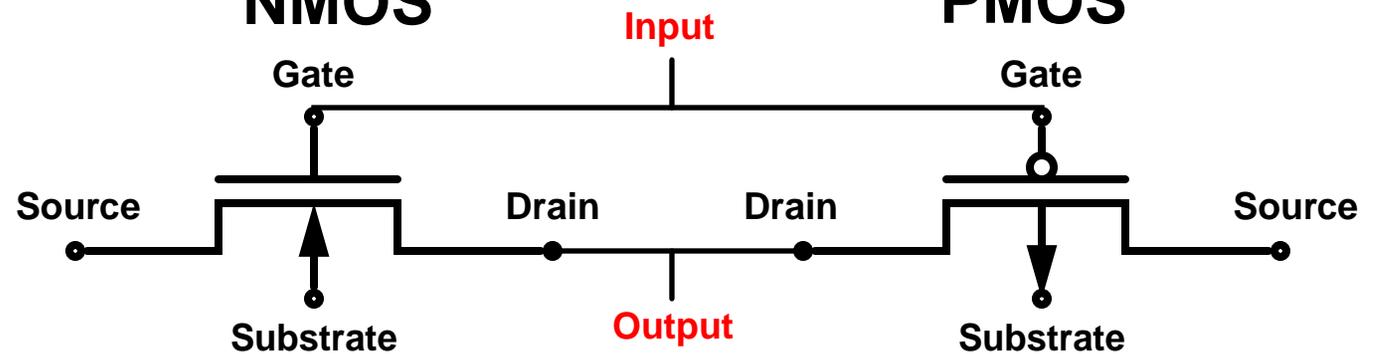
How Is It Done? (devices)

MOS Transistors:

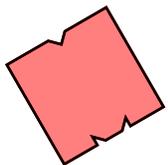


NMOS

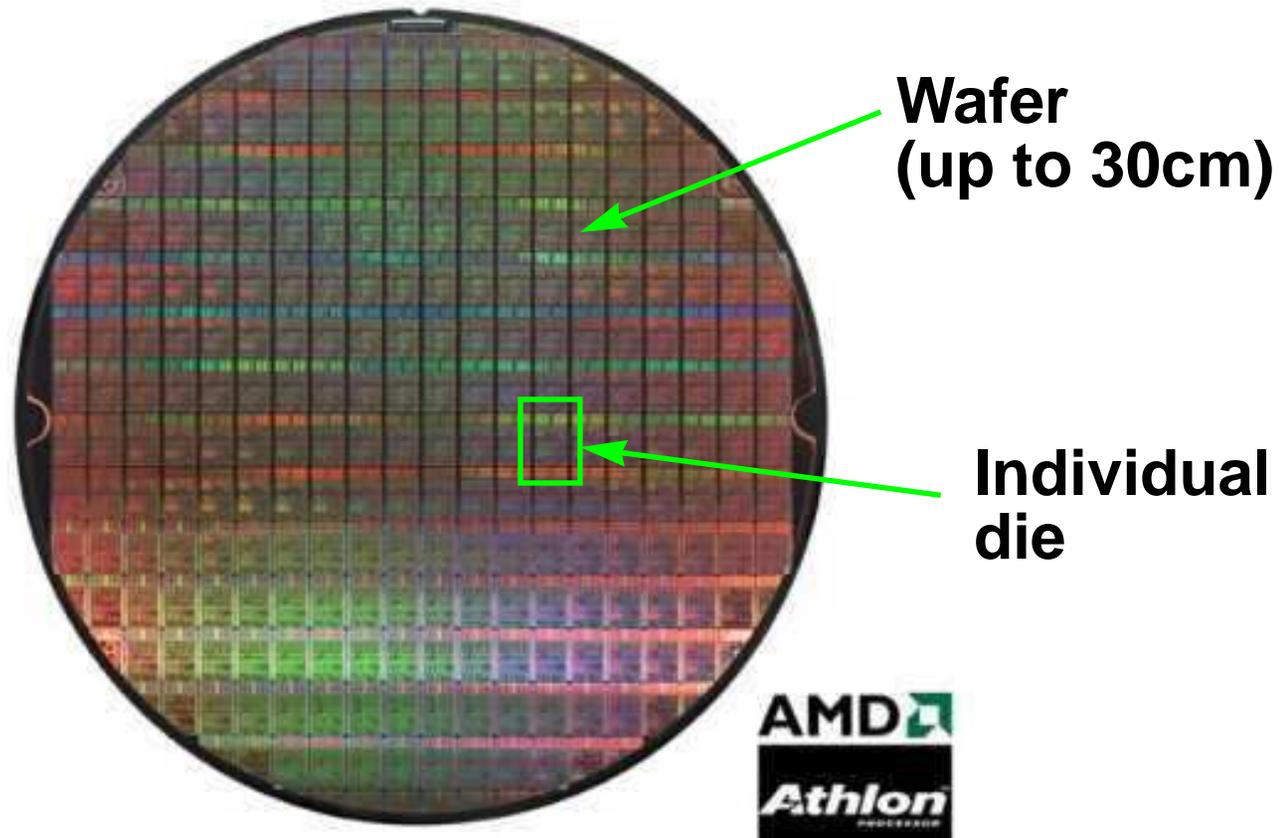
PMOS



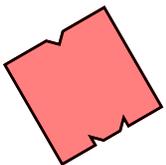
CMOS Inverter = one of each



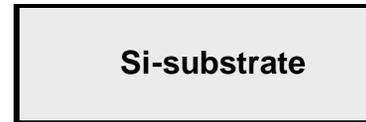
How ...? (manufacturing)



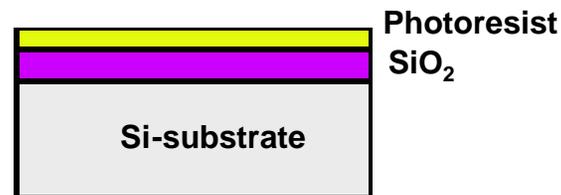
**Wafer is a thin slice off a silicon log;
Each wafer produces many identical chips**



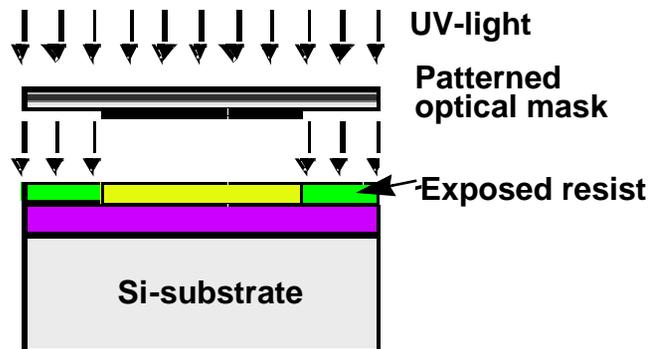
How ...? (manufacturing)



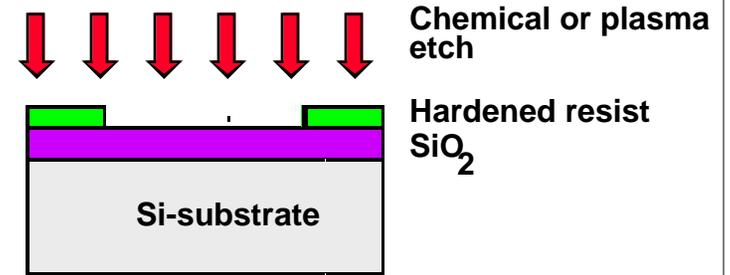
Silicon base material



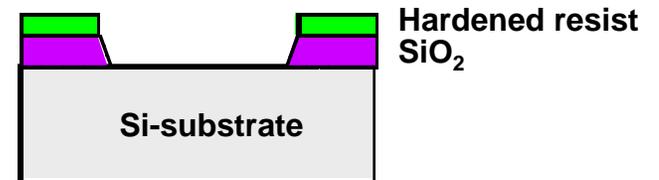
1&2. After oxidation and deposition of negative photoresist



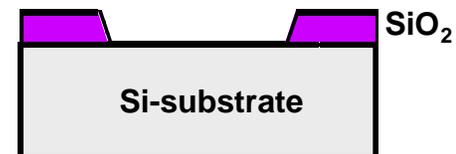
3. Stepper exposure



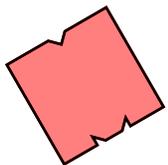
4. After development and etching of resist, chemical or plasma etch of SiO₂



5. After etching



8. Final result after removal of resist

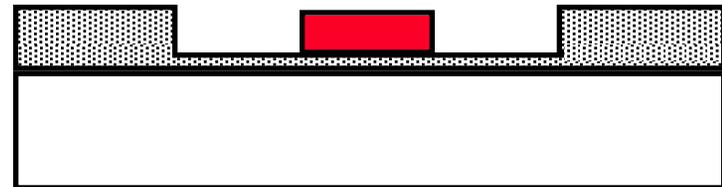


How ...? (manufacturing)

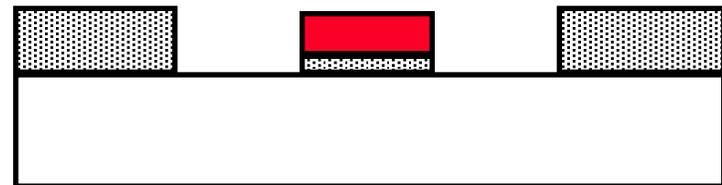
1. Create thin oxide in the “active” regions, thick elsewhere



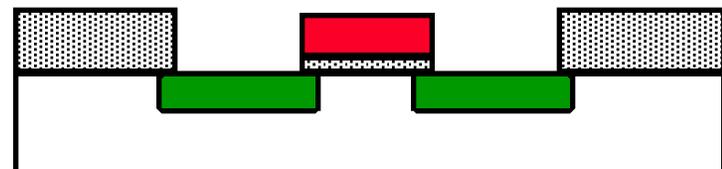
2. Deposit polysilicon



3. Etch thin oxide from active region (poly acts as a mask for the diffusion)

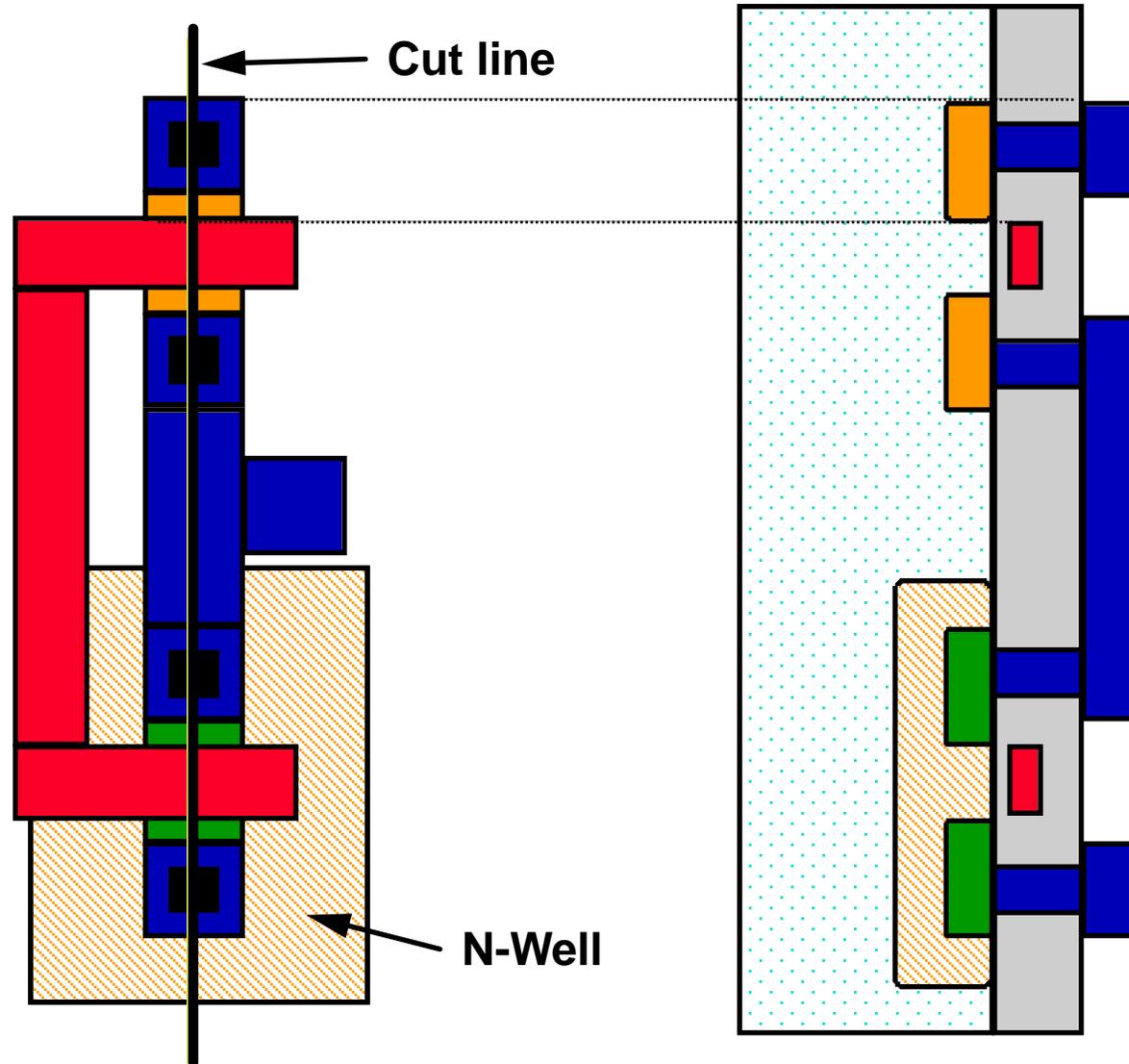


4. Implant dopant

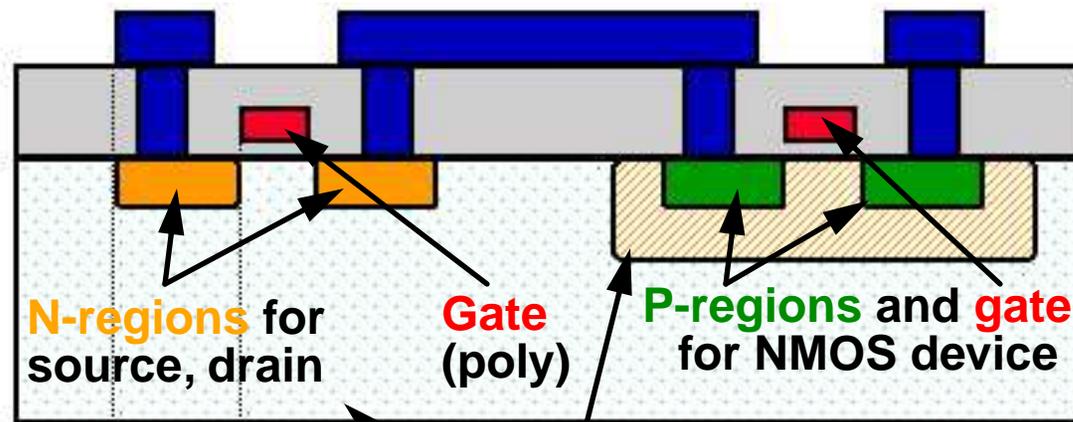


How ...? (manufacturing)

CMOS Inverter



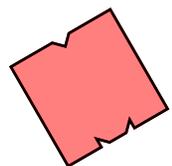
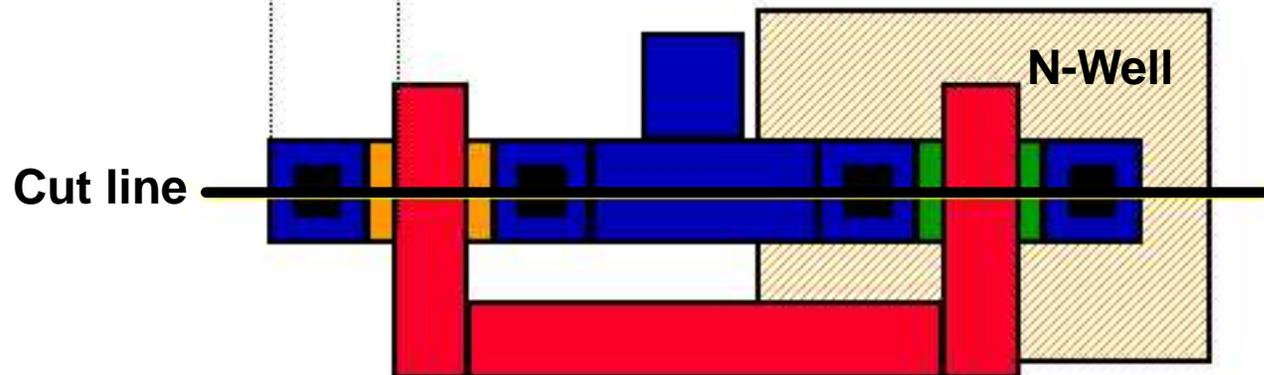
How ...? (manufacturing)



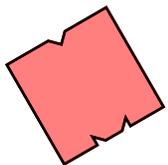
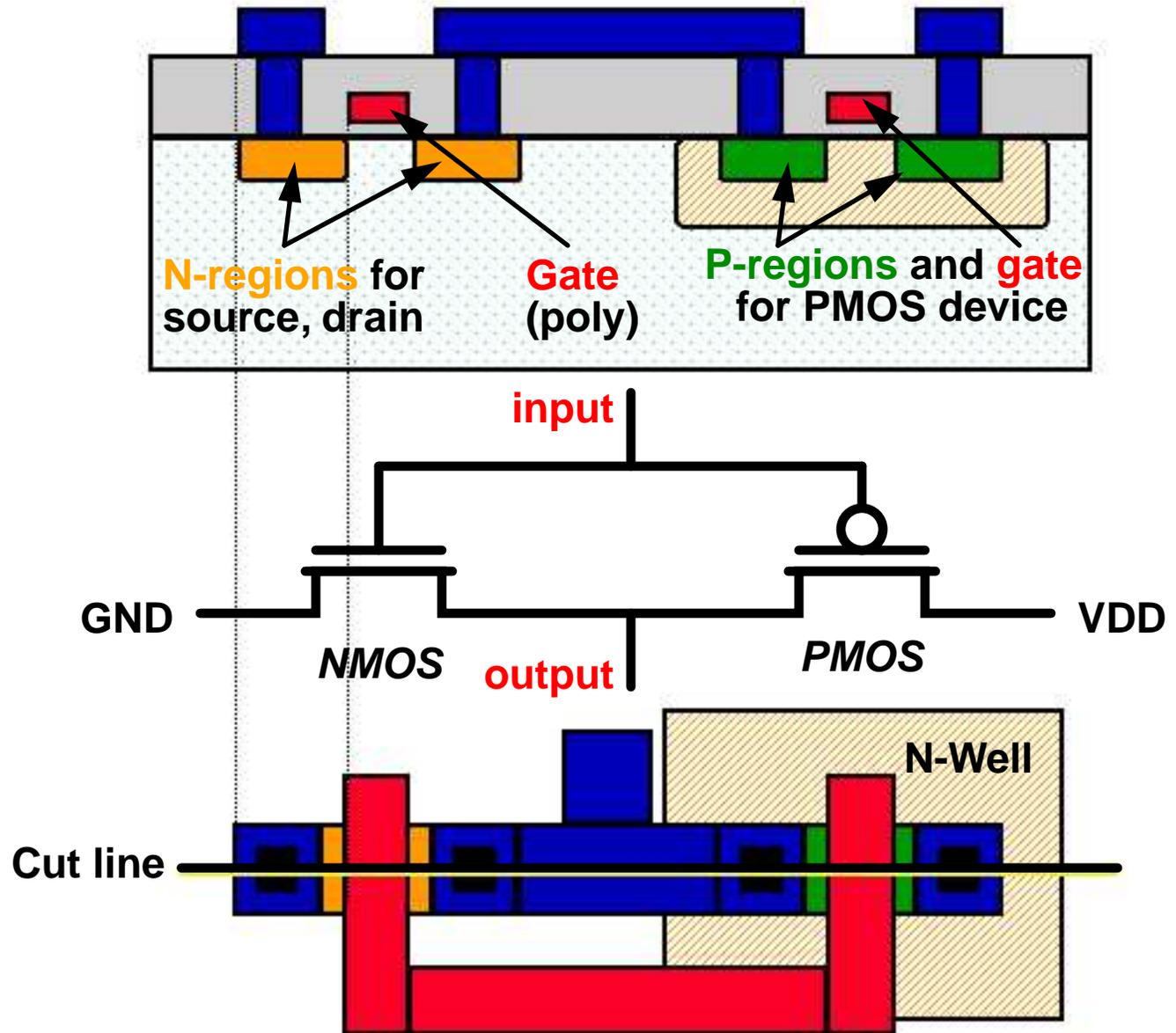
N-Well ("n-well process")

P-type wafer

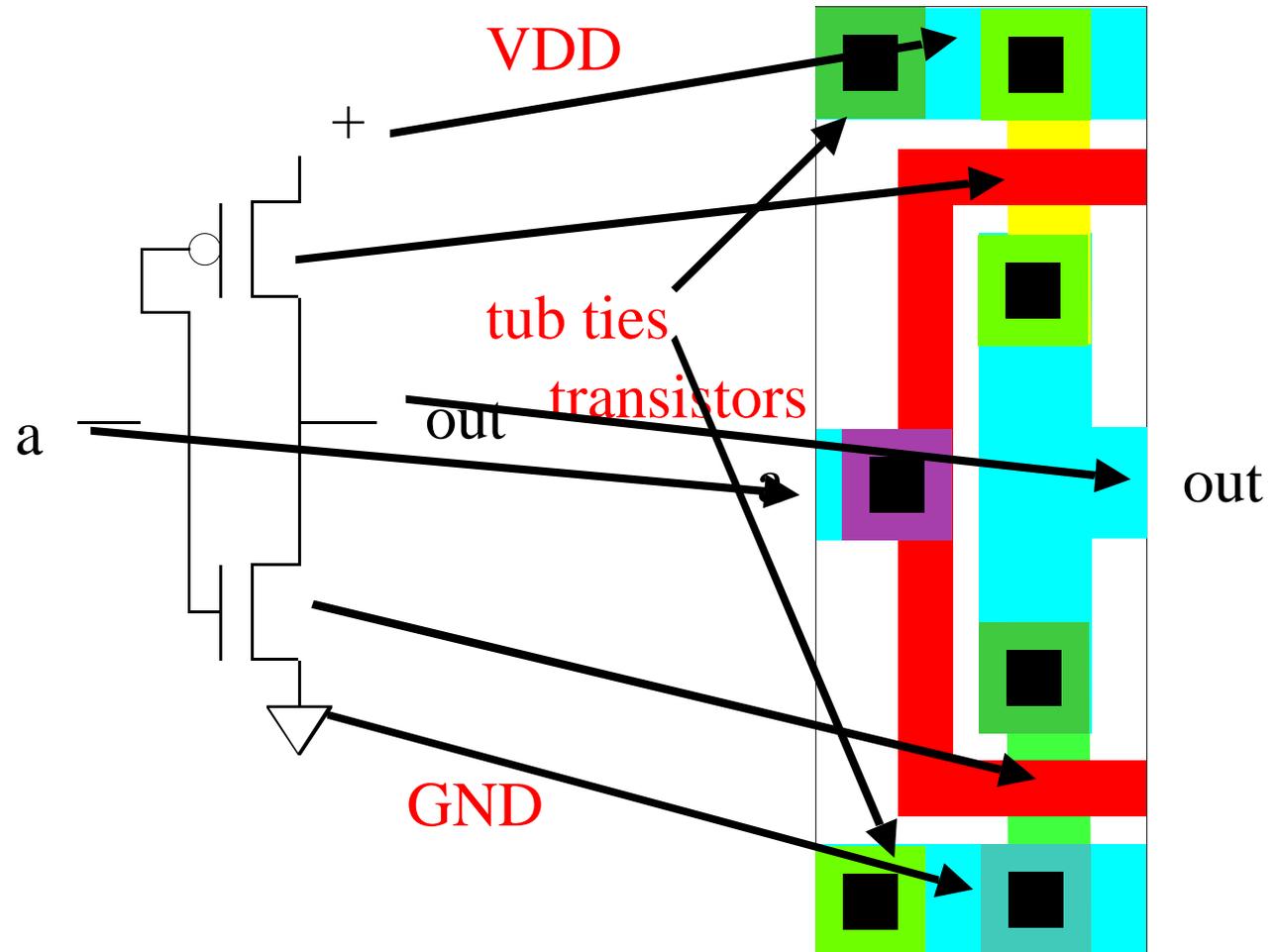
CMOS Inverter



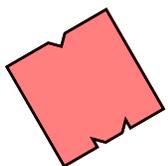
How ...? (manufacturing)



How ...? (manufacturing)

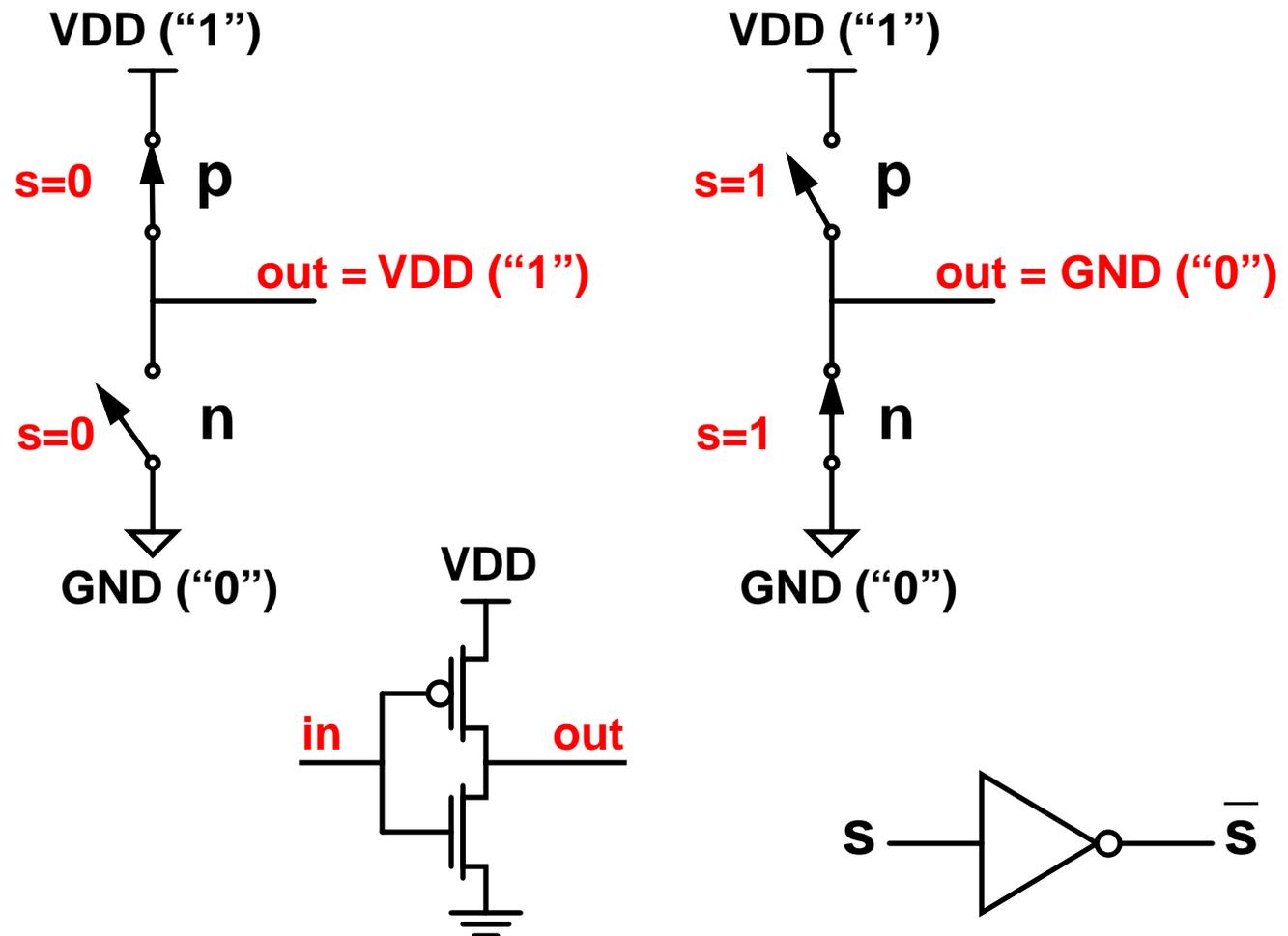


Another view (note: wells/tubs not shown)



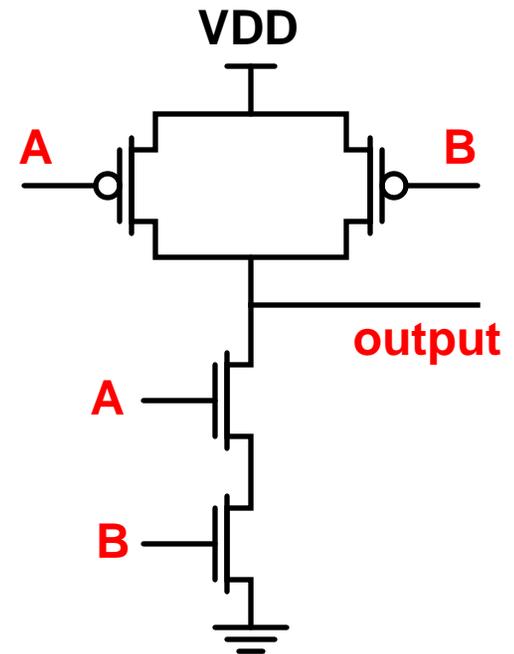
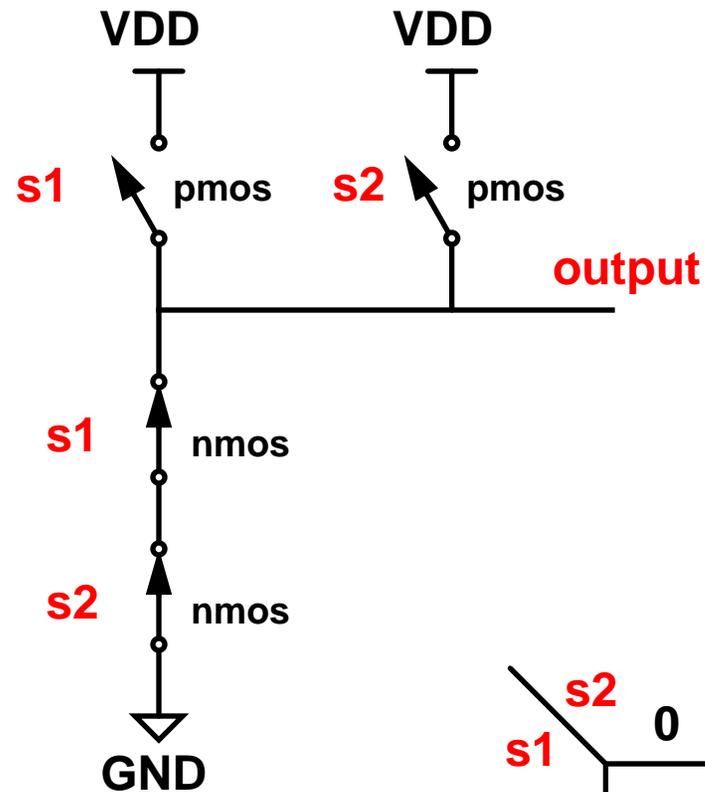
How Is It Done? (logic)

CMOS Inverter

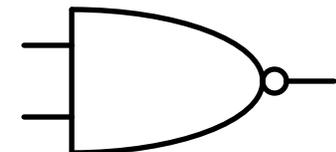


How Is It Done? (logic)

CMOS NAND-gate

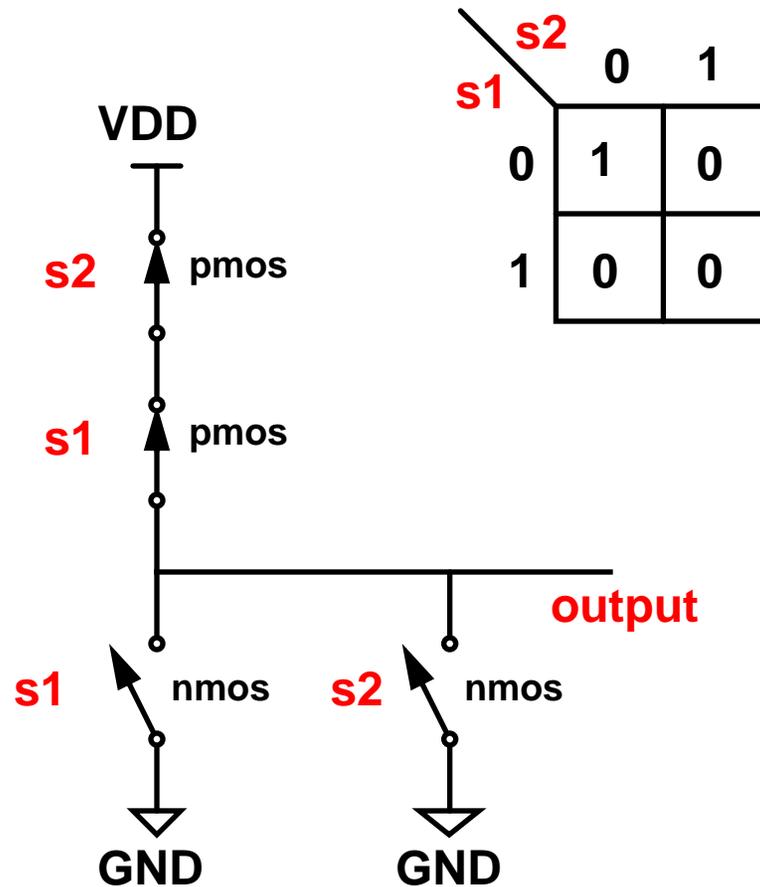


	s2	0	1
s1	0	1	1
1	1	0	

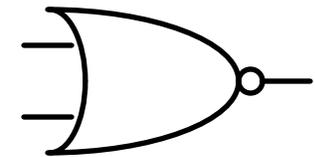
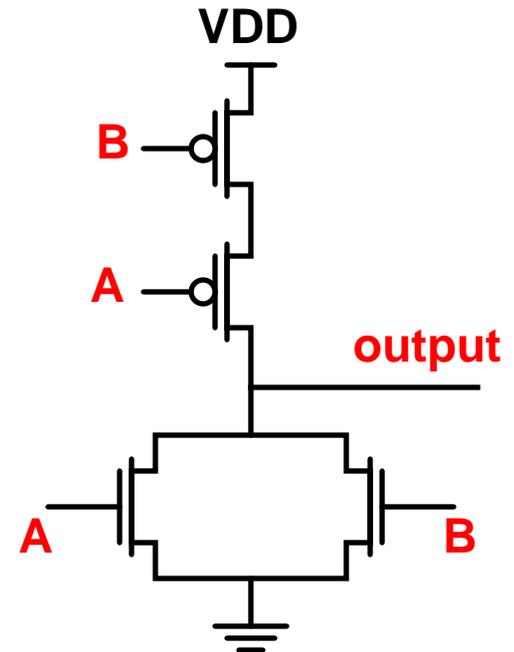


How Is It Done? (logic)

CMOS NOR-gate

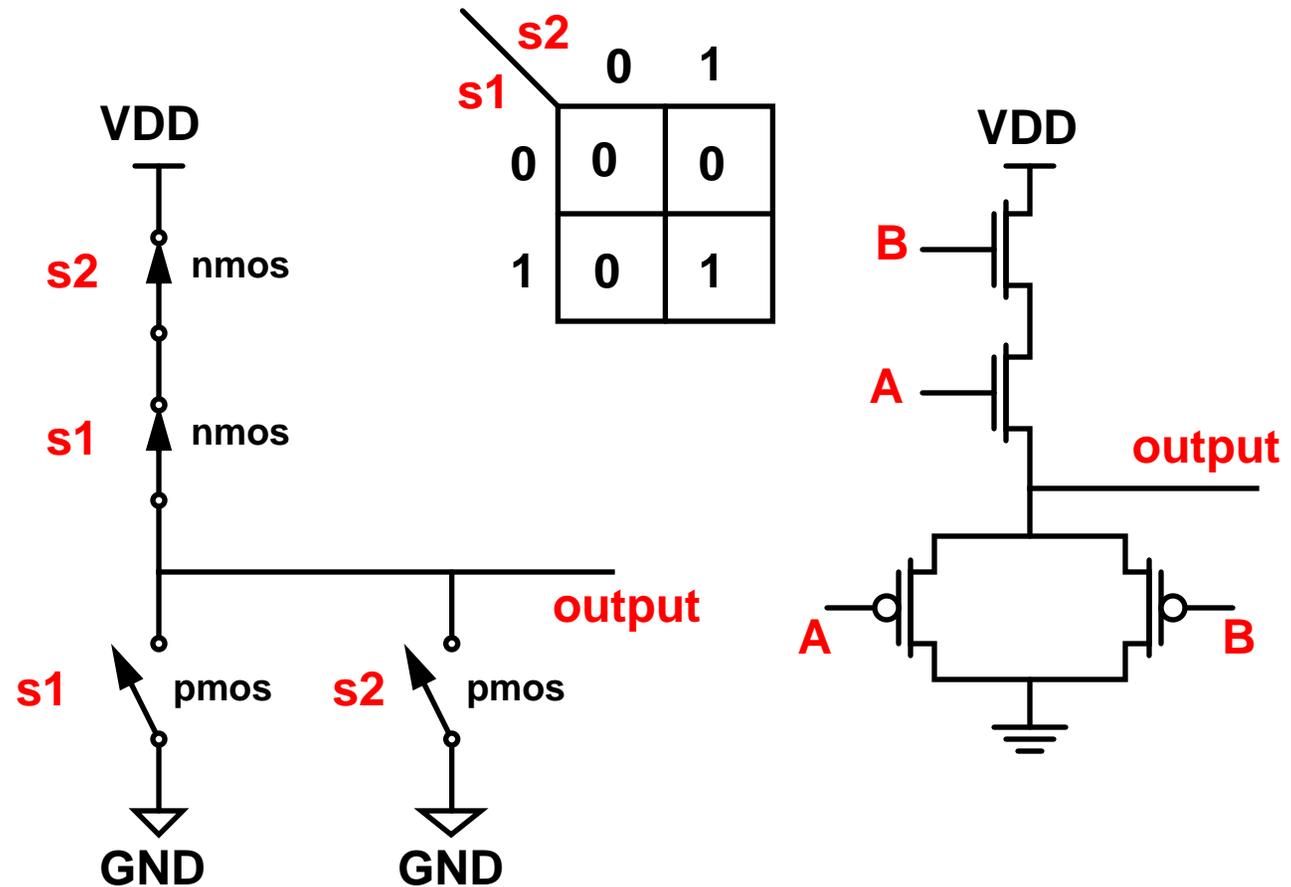


	s2	0	1
s1	0	1	0
1	0	0	0

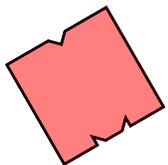


How Is It Done? (logic)

CMOS *AND*-gate?



TEMPTING, BUT BAD IDEA (why?)



How Is It Done? (design)

Big change in industry, late 1970's:

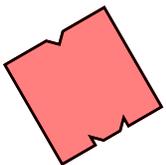
Mead & Conway introduced *design rules*

**Previous to this, all IC work was by hand,
and integration of components was at the
chip level (CPU = tons of connected chips)**

Design rules enabled CAD tools

Popular (and powerful) tools today:

- **Cadence tools (behavioral-to-layout)**
- **Synopsys tools (synthesis)**
- **HSPICE (circuit simulation)**



How ...? (tools: verilog)

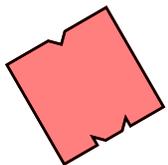
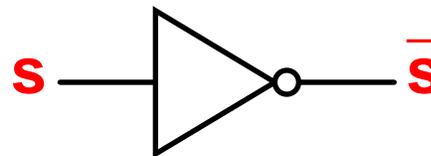
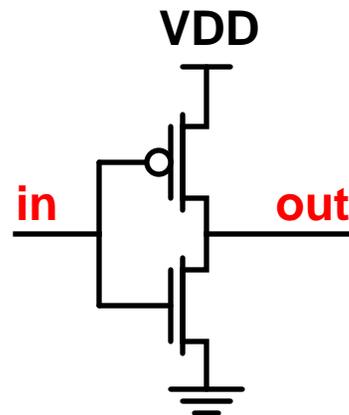
The Many Faces of *NOT* (*inverter*)

Structural Verilog:

```
wire s;  
wire sbar;  
NOT not1(s, sbar);
```

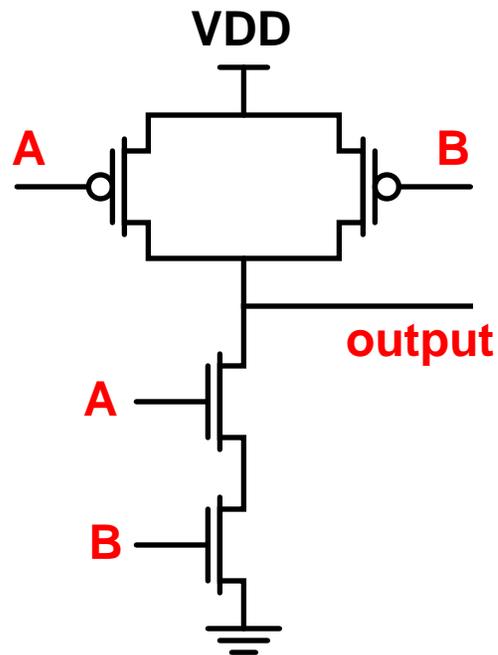
Behavioral Verilog:

```
wire s, sbar;  
sbar = ~s;
```



How ...? (tools: verilog)

The Many Faces of *NAND*

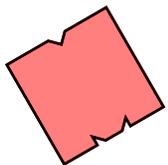
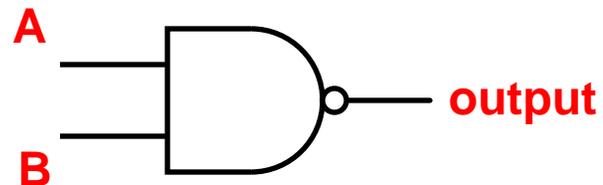


Structural Verilog:

```
wire a, b;  
wire out;  
NAND nand1(a, b, out);
```

Behavioral Verilog:

```
wire a, b, out;  
out = ~(a & b);
```



How ...? (tools: synopsys)

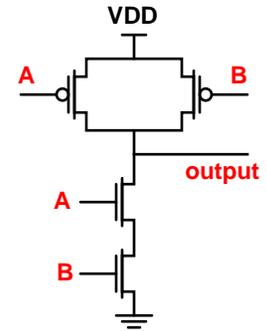
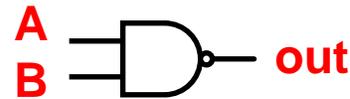
Logic synthesis: *Behavioral* -> *Structural*

```
wire a, b, out;  
out = ~(a & b);
```

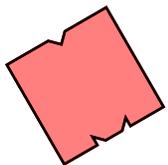
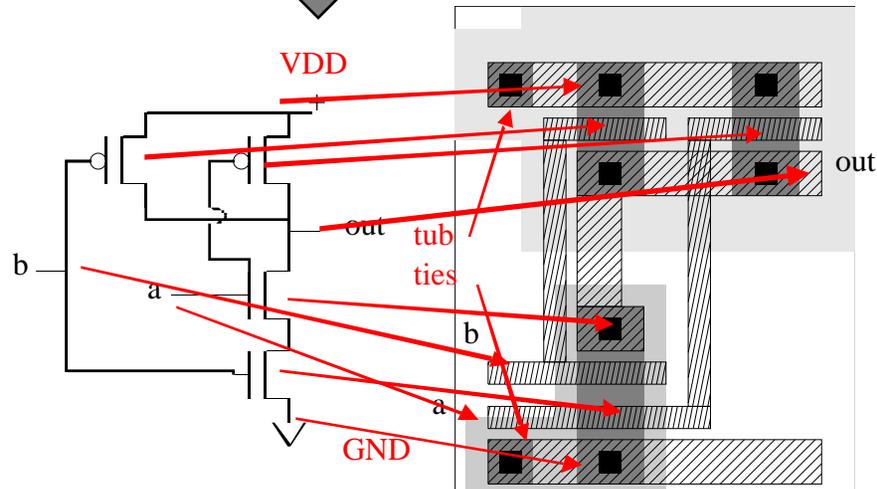
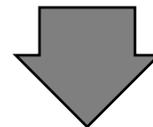
Logic Synthesis



```
wire a, b;  
wire out;  
NAND nand1(a, b, out);
```



Library Instantiation

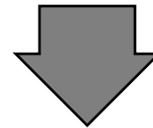


How ...? (tools: synopsys)

Logic synthesis: *Behavioral -> Structural*

```
wire a, b, c, out;  
out = ~((a & b) | c);
```

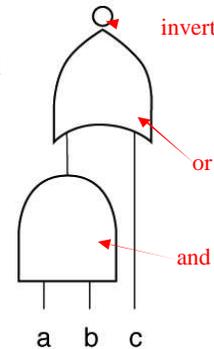
Logic Synthesis



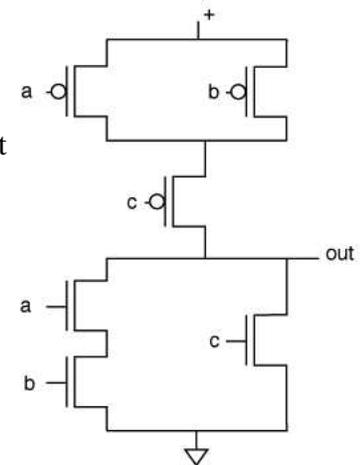
```
wire a,b,c,out;  
wire t1,t2;  
AND and1(a,b,t1);  
OR or1(c,t1,t2);  
NOT not1(t2,out);
```

out = [ab+c]̄

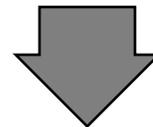
symbol



circuit



Library Instantiation



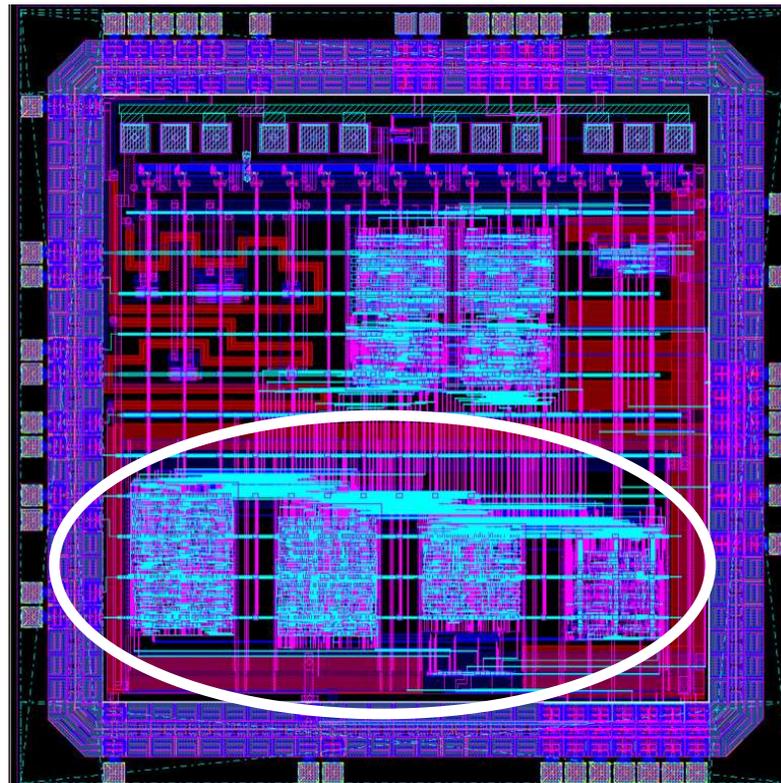
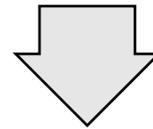
LAYOUT



How ...? (tools: synopsys)

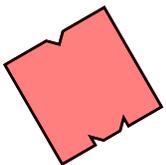
The tool will provide design options ...

```
wire a, b, out;  
out = a + b;
```

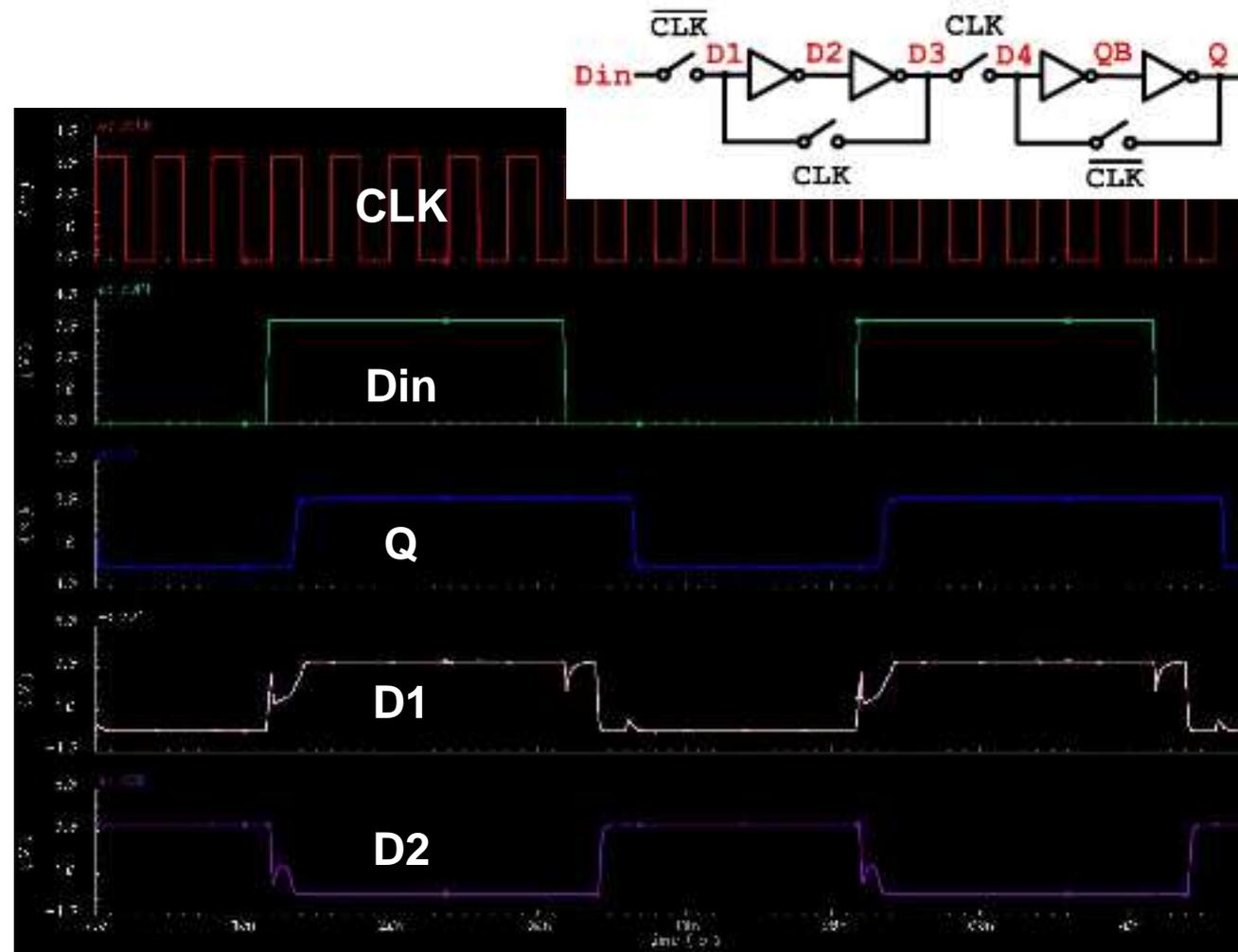


Four Adders:

- *Ripple*
- *Brent-Kung*
- *Carry-Lookahead*
- *Fast Carry-Lookahead*



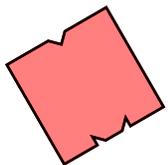
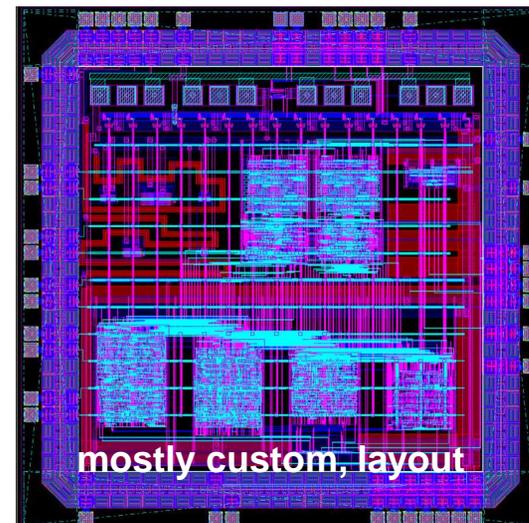
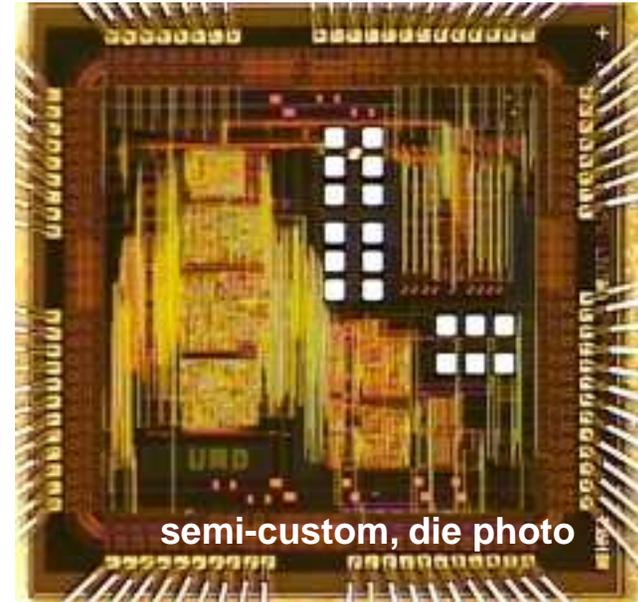
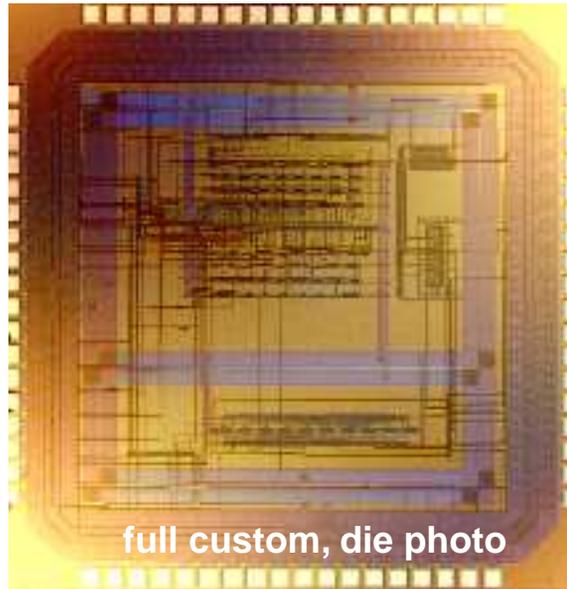
How ...? (tools: HSPICE)



Very accurate simulation of circuits



How ...? (tools: cadence)



How Is It Done? (design flow)

Begin with a Behavioral Description:

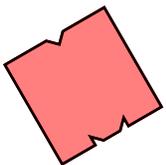
```
module testcounter(clk2, rst_1, out_w);

input clk2, rst_1;
output[7:0] out_w;

reg [7:0] srcl, out;
wire [7:0] out_w = out;

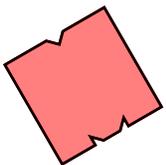
always @(posedge clk2)
begin
    if(!rst_1)
        begin
            srcl <= 1'd0;
            out <= 1'd1;
        end
    else
        begin
            srcl <= out_w;
            out <= srcl + out_w;
        end
    end
end

endmodule
```



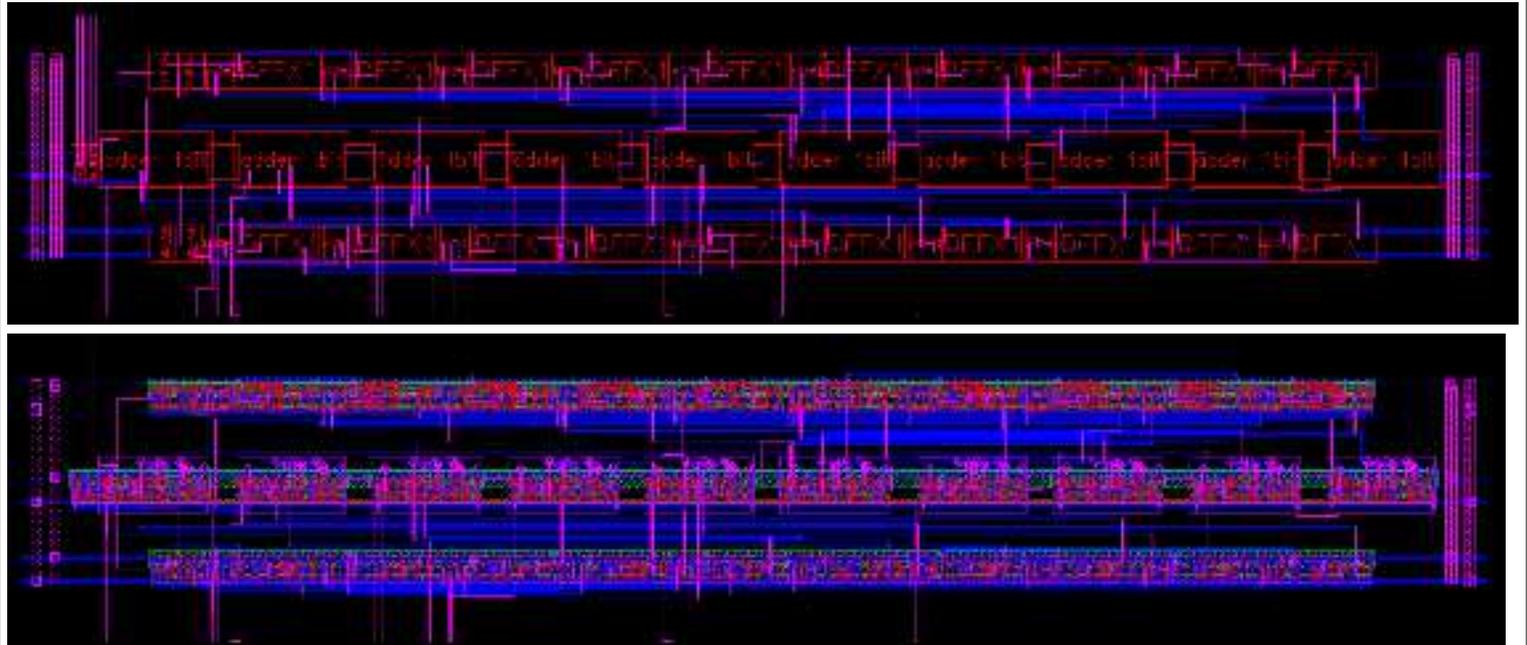
How Is It Done? (design flow)

Logic synthesis produces gate-level netlist:

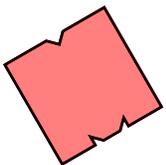


How Is It Done? (design flow)

Instantiation of physical design libraries & place+route yields Physical Layout:

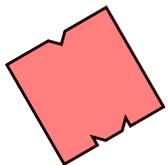
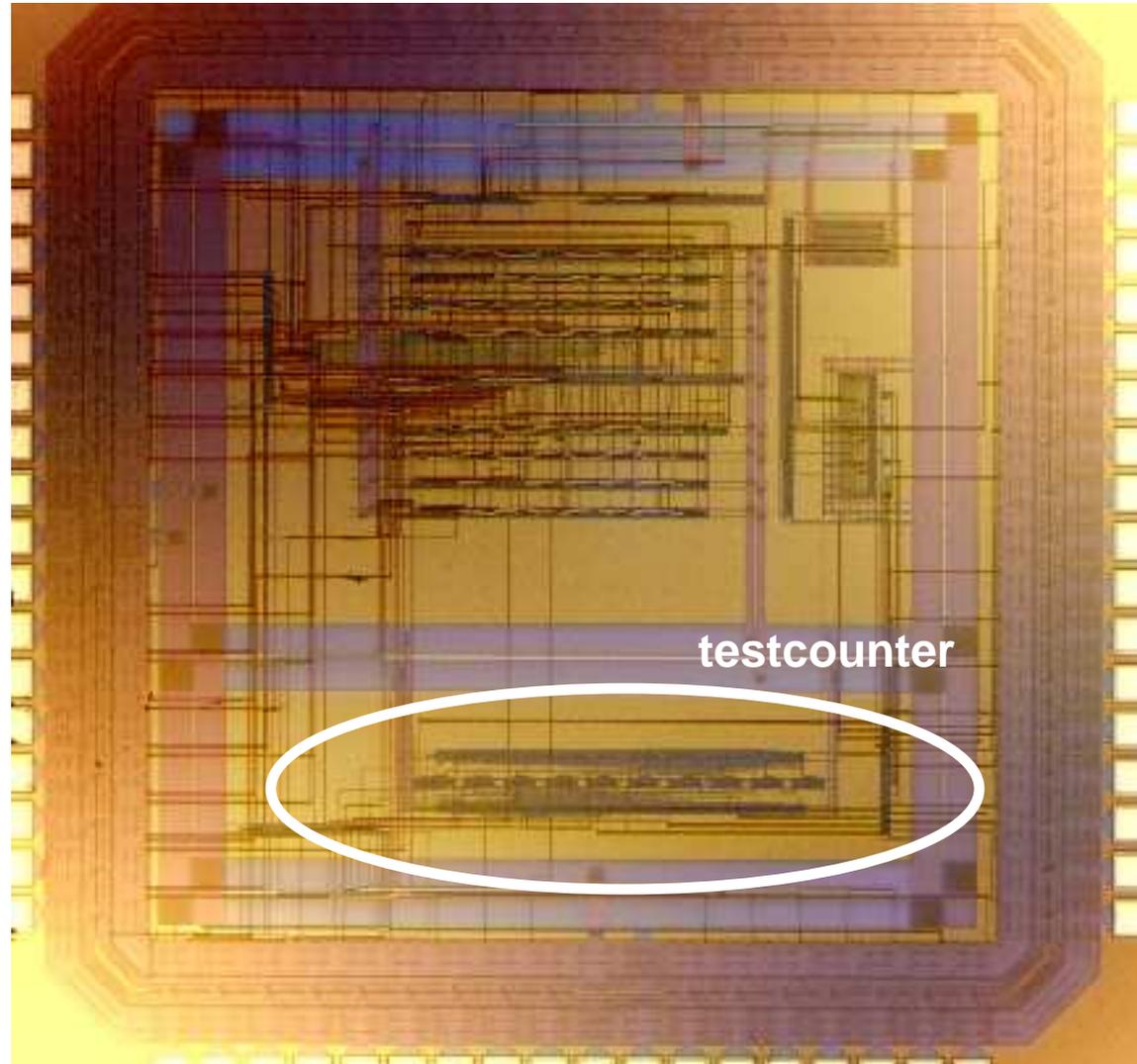


(two views shown: one with black boxes for high-level structures like flip-flops/adders/MUXes, the other showing all transistors and wires)

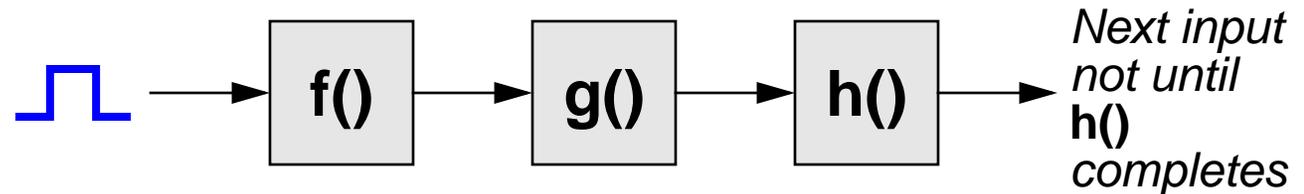


How Is It Done? (design flow)

Send to fabrication facility, receive Chip:



How Is It Done? (system)



Simplest possible system-building scheme:

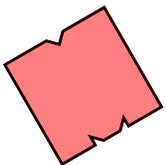
Sequential—Do One Thing At a Time

Advantages:

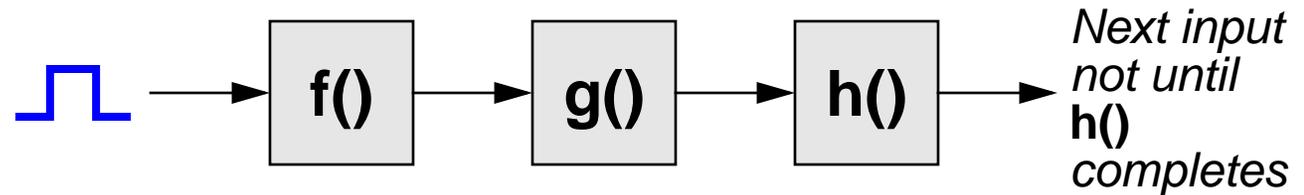
- **Simple, predictable, easy to debug**

Disadvantages:

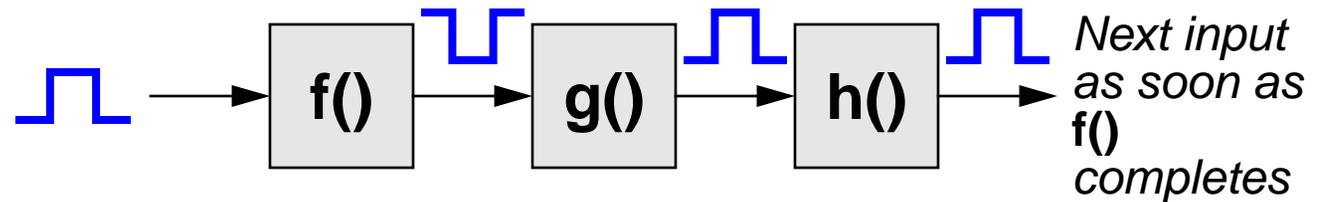
- **Slow, wastes hardware (g & h blocks idle while f computes, f & h blocks idle while g computes, etc.)**



How Is It Done? (system)



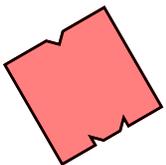
VERSUS



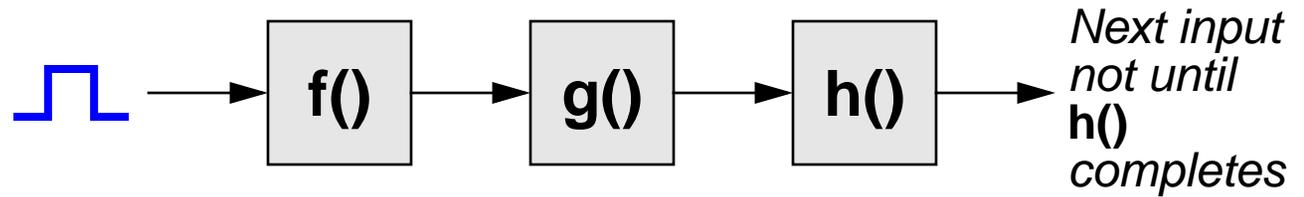
Called a **PIPELINE**: extremely common

- Hardware used as fully as possible
- Throughput increases n-fold (n blocks)

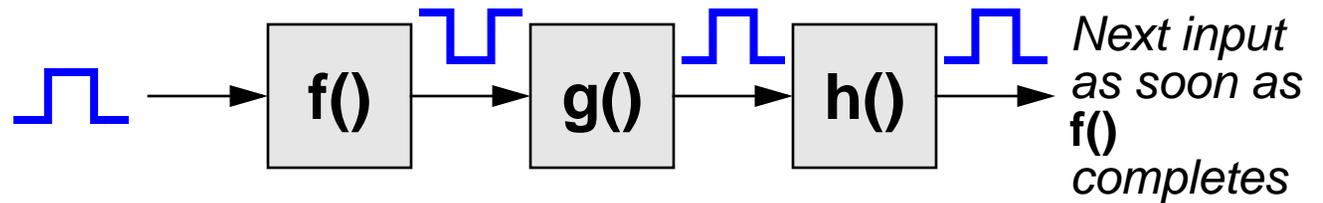
Question: How to control this?



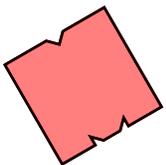
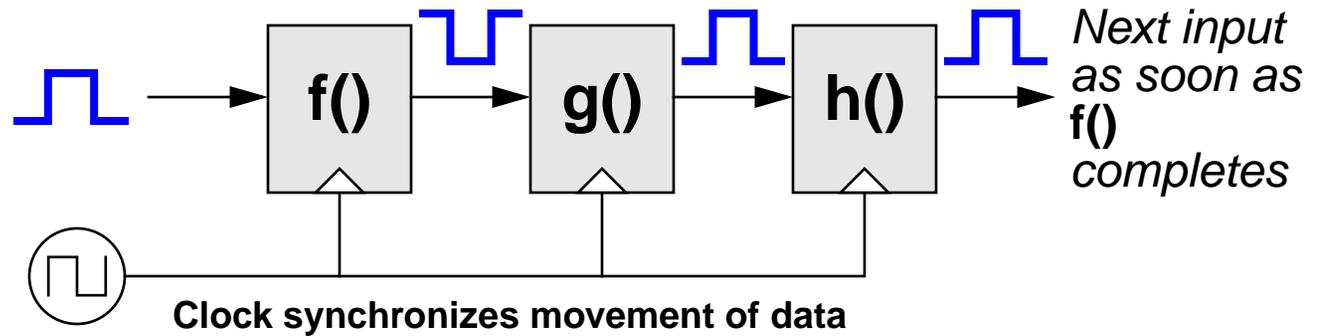
How Is It Done? (system)



VERSUS



Control: Think *traffic in a city* (stop lights)



What Are The *Gotcha's*?

“High-speed digital design, in contrast to digital design at low speeds, emphasizes the behavior of passive circuit elements. These passive elements may include the wires, circuit boards, and integrated-circuit packages that make up a digital product. At low speeds, passive circuit elements are just part of a product’s packaging. At higher speeds the directly affect electrical performance.”

— opening par. of Johnson & Graham, High-Speed Digital Design

The bottom line:

At high speeds, digital systems (which diverged from analog: simpler, remember?) start to behave *just like analog systems.*



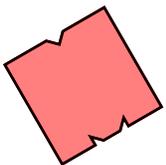
What Are The *Gotcha's*?

HIGH-SPEED DESIGN exposes problems:

- Even small amounts of **NOISE**
- Even small amounts of **DELAY**
- Even small amounts of **CURRENT**

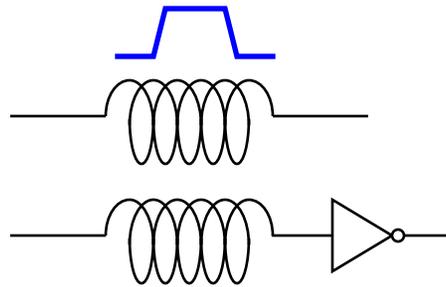
... can cause a circuit to misbehave.

- At high speeds, signal levels are small (small noise levels become significant)
- At high speeds, event timing is tight (small errors in time become significant)
- At high speeds, current changes quickly (even if di is small, Ldi/dt can be large)

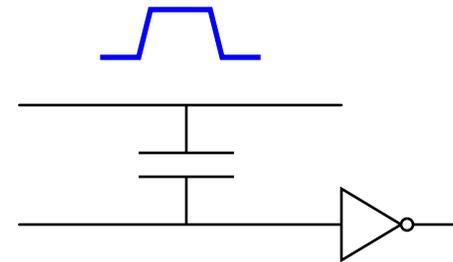


Gotcha's? (noise)

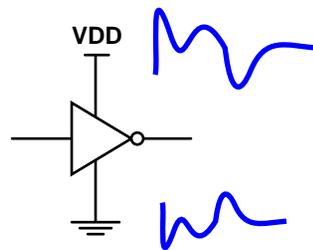
Typical noise sources:



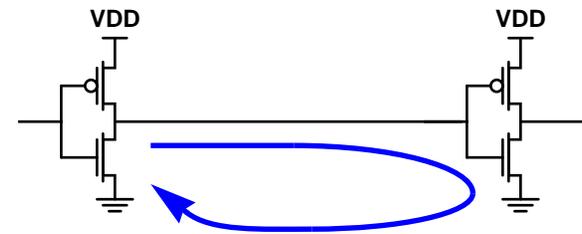
Inductive coupling



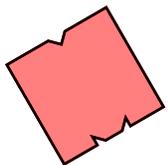
Capacitive coupling



Groundplane noise

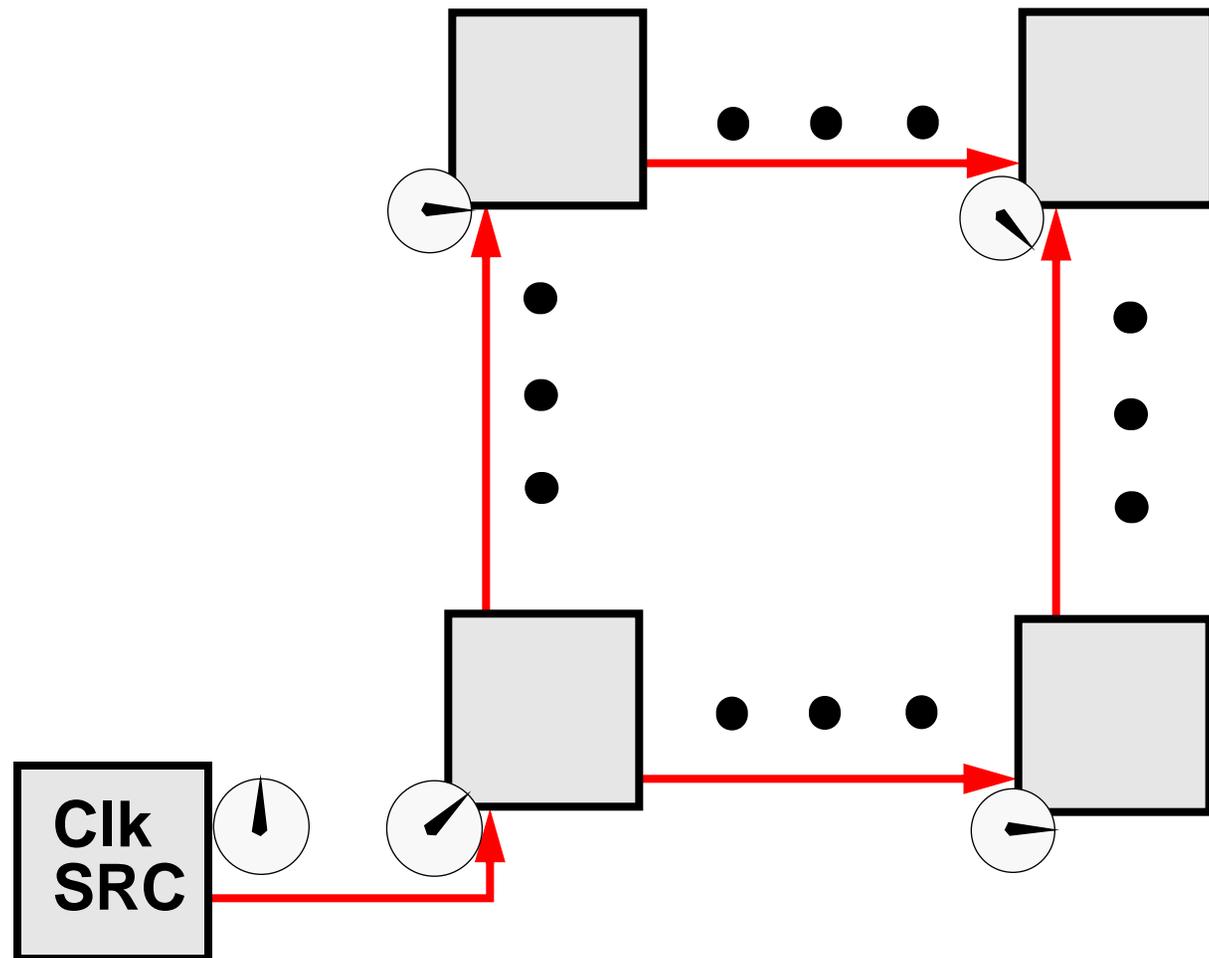


**Implicit/explicit circuits (current return)
make great radiators and antennae**



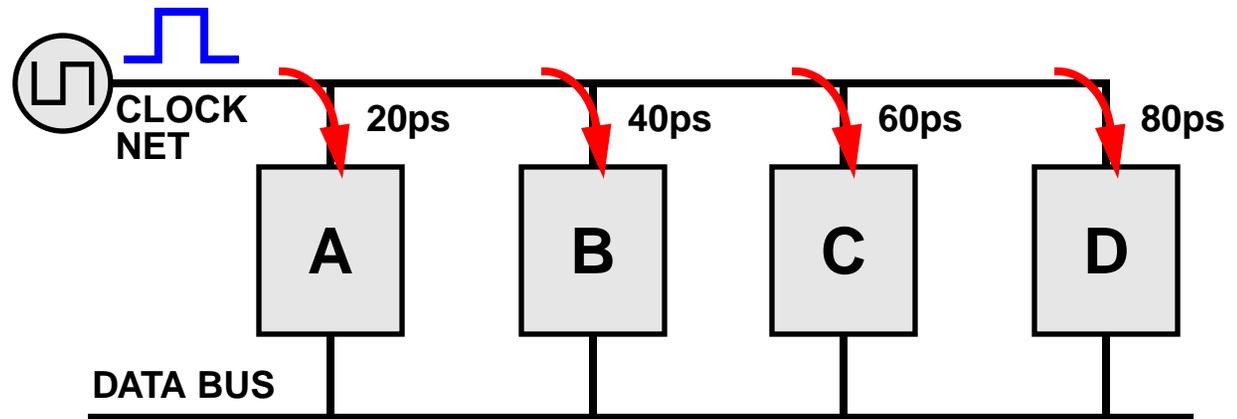
Gotcha's? (delay)

Though we like to imagine that it is,
signal propagation is not instantaneous

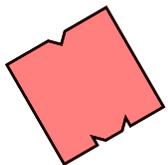
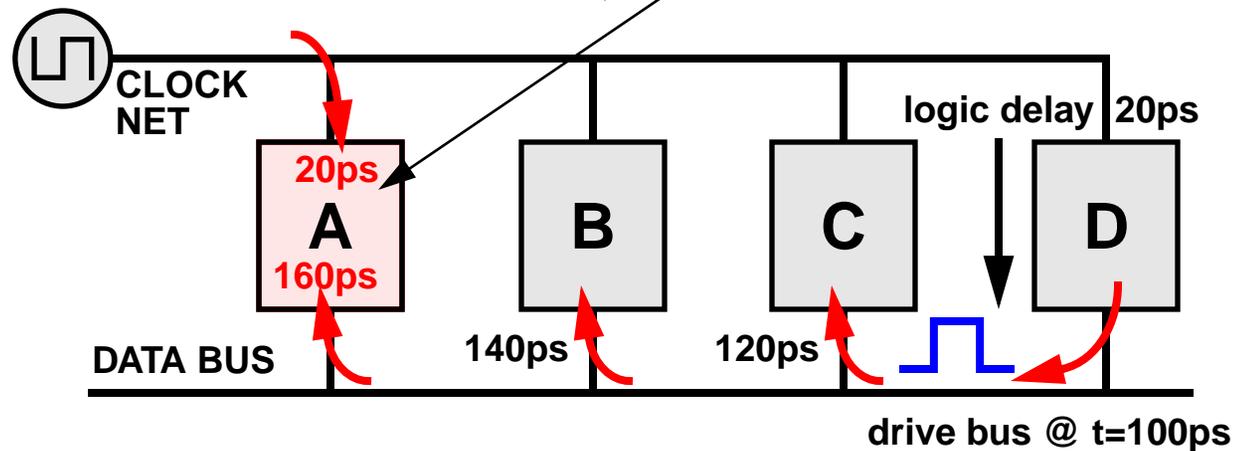


Gotcha's? (delay)

Argument for source-synchronous clocking:

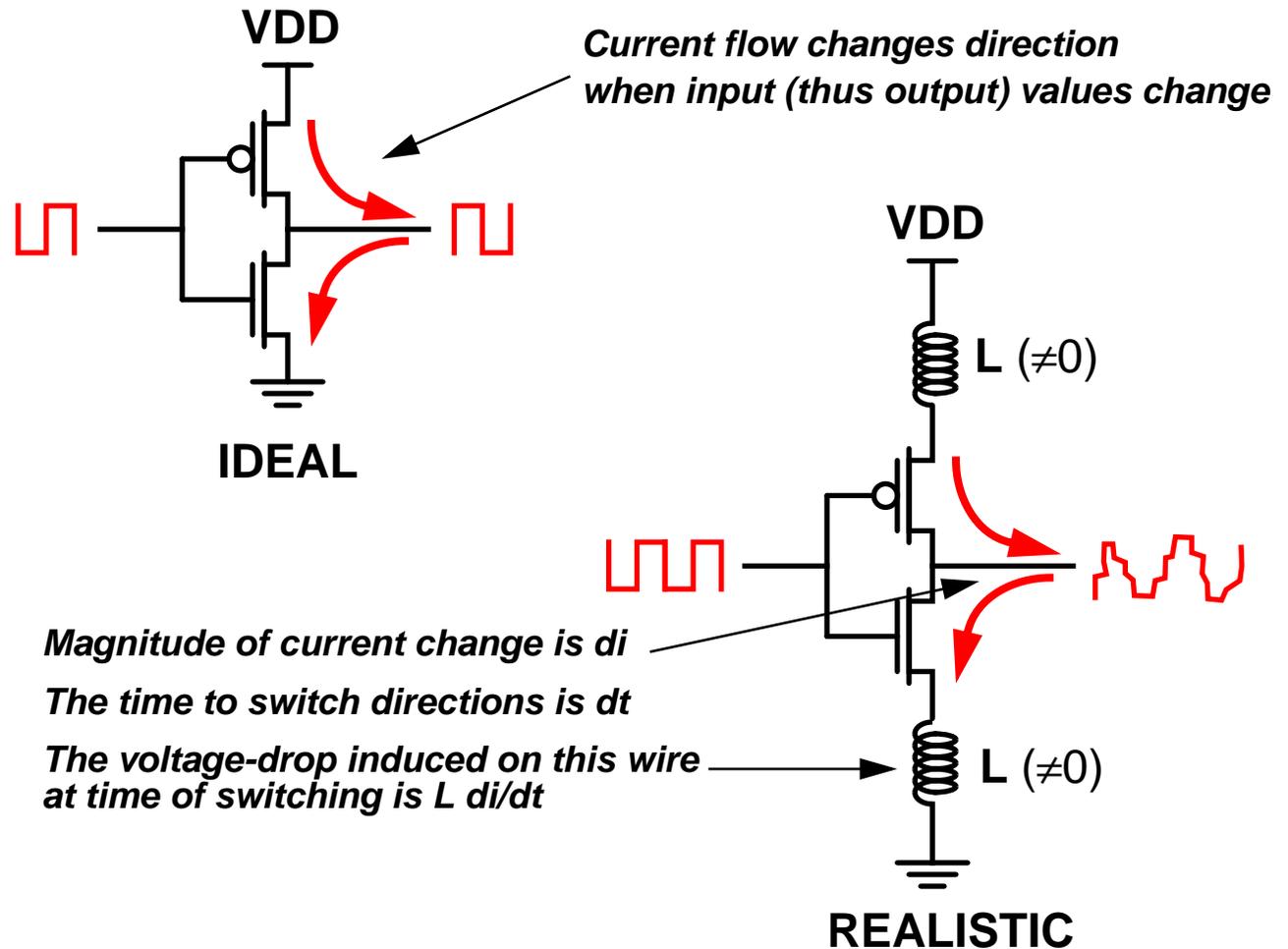


if CLK is used to sample data*, this adds 0.14ns to uncertainty
(*def'n: tell A when to look at data bus)



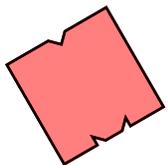
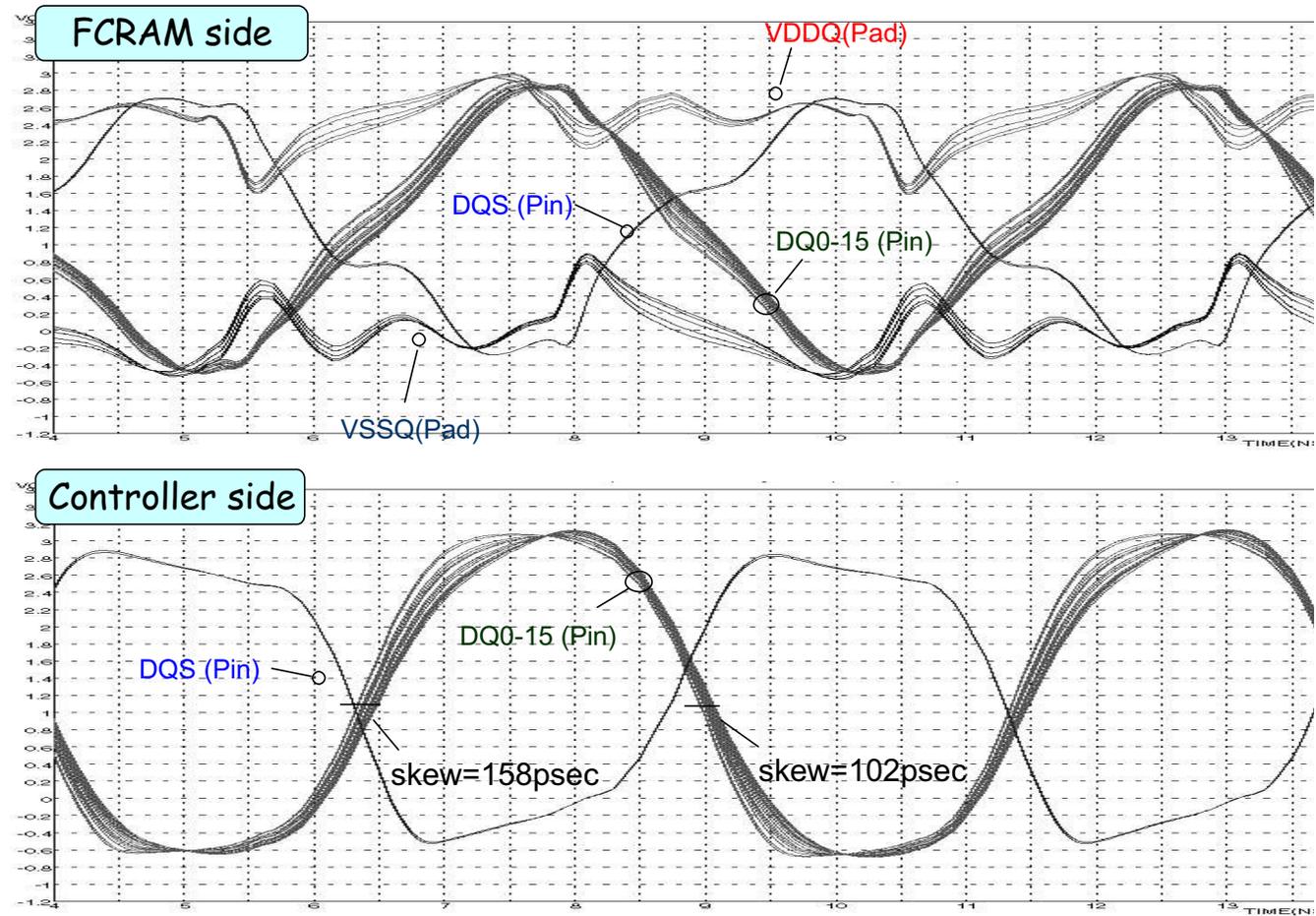
Gotcha's? (current)

Ideal Scenario vs. Reality (ground bounce):



Gotcha's? (current)

Simultaneous Switching Noise:



What Are Some Solutions?

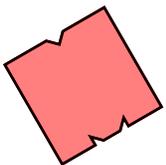
IN GENERAL:

Prevent the Problem

- Design as if the problem doesn't exist (continue using same old techniques as you did with low-speed designs)
- Use mechanism to counteract problem

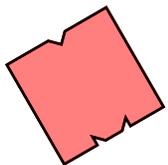
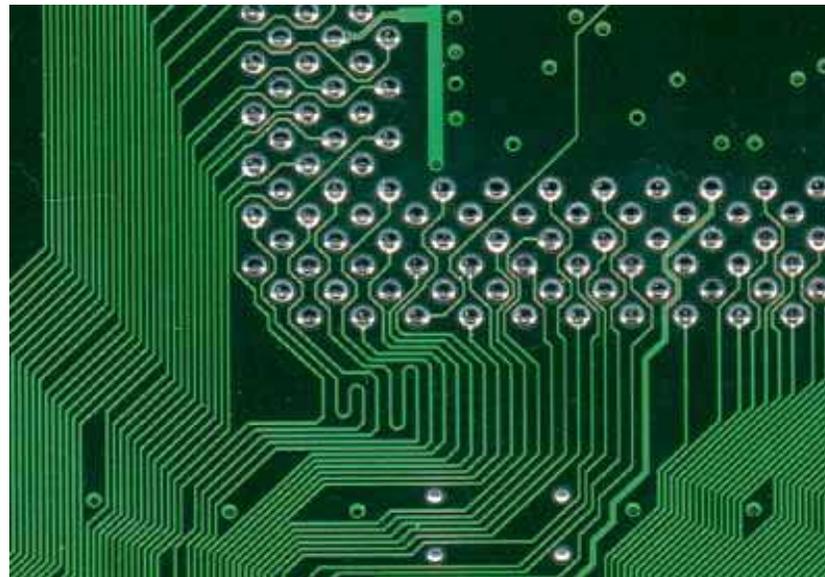
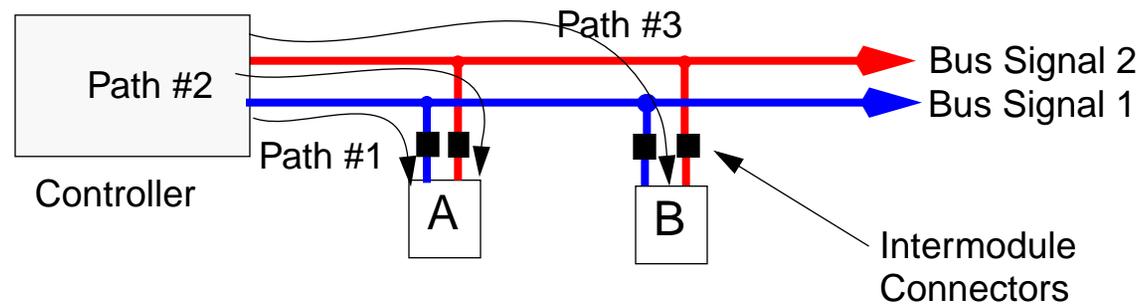
Design Around the Problem

- Re-think the way you design systems: *assume the problem happens; ensure that it doesn't affect design* (design makes no assumptions re: problem)
- Don't need to counteract problem



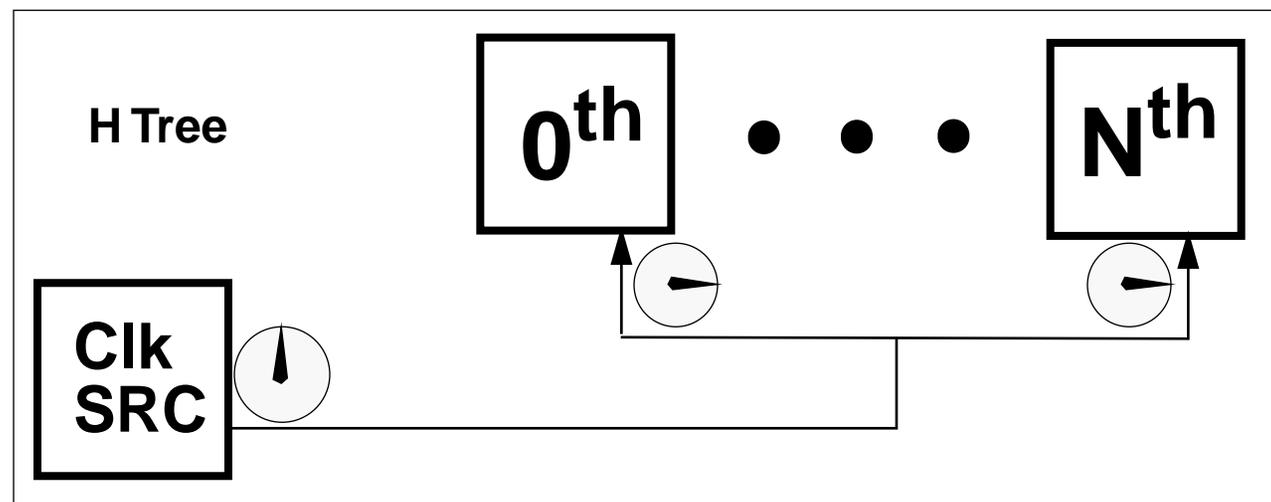
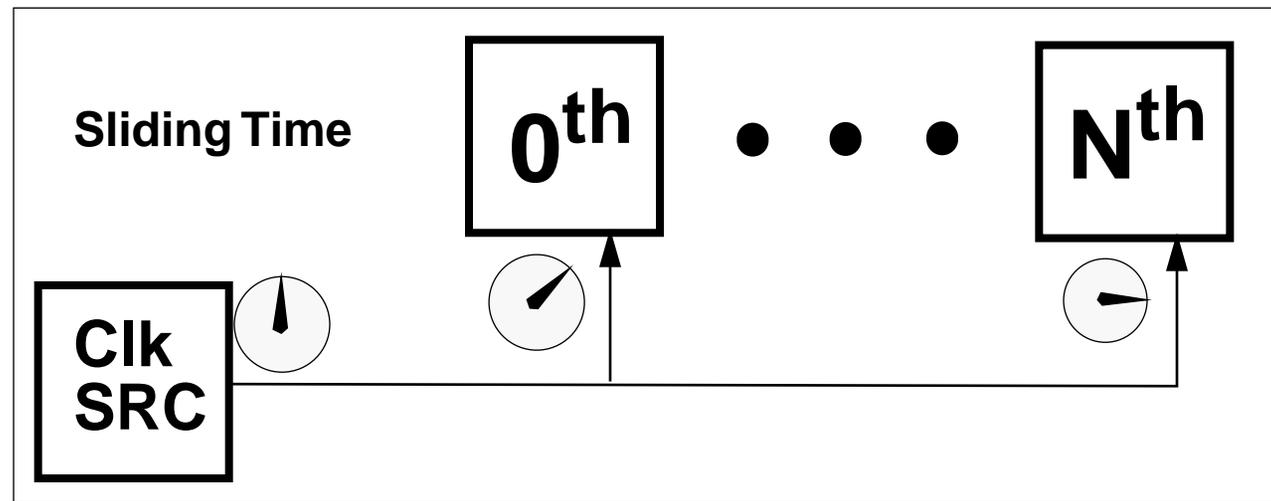
What Are Some Solutions?

One solution to delay problem:
heroic routing



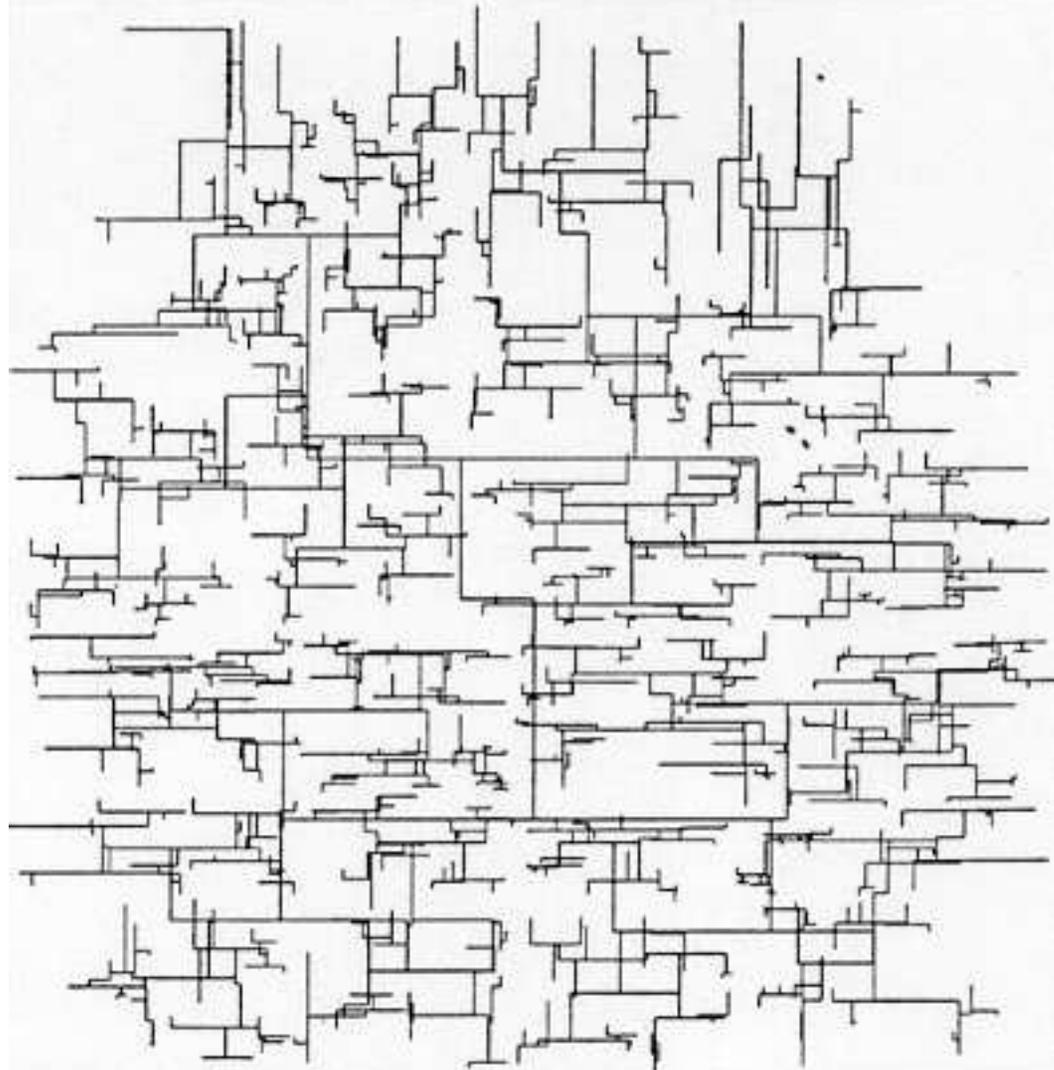
What Are Some Solutions?

Another solution to the delay problem



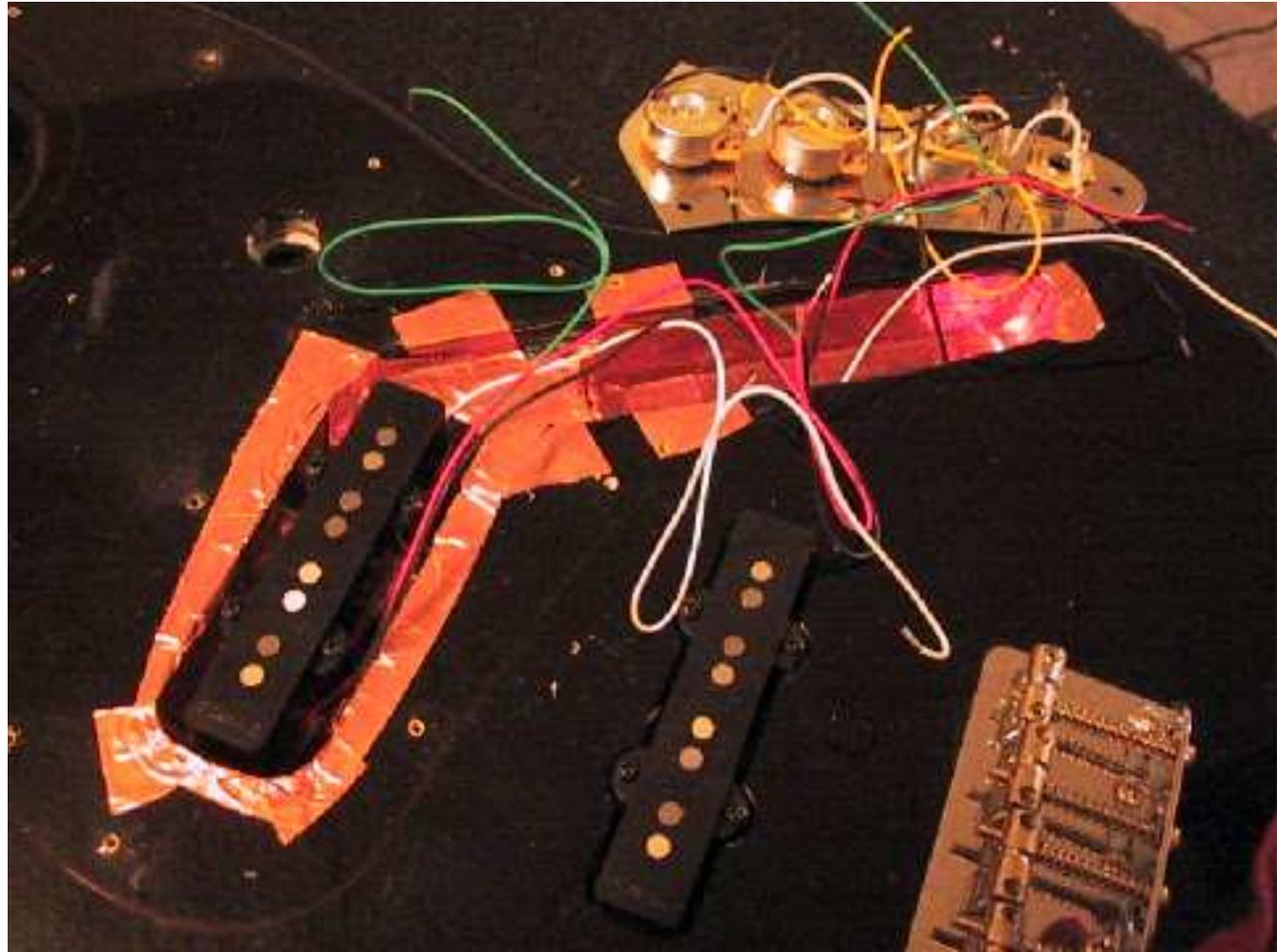
What Are Some Solutions?

(clock trees work, but may be better sol'ns?)



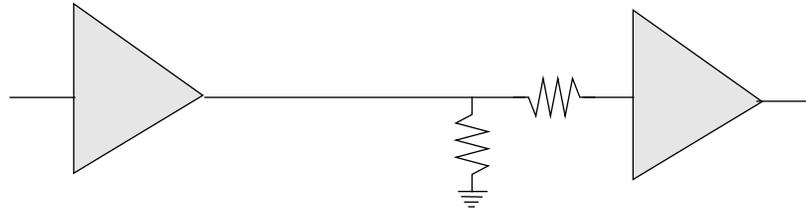
What Are Some Solutions?

One solution to noise problem (shielding):

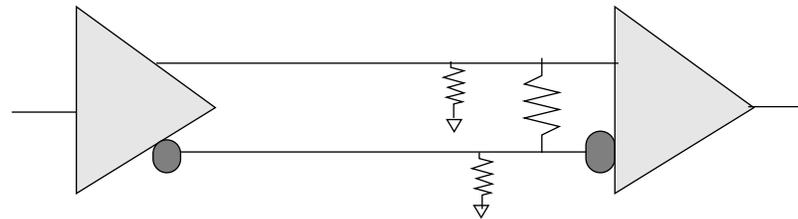


What Are Some Solutions?

Another solution to the noise problem:



Single Ended Transmission Line

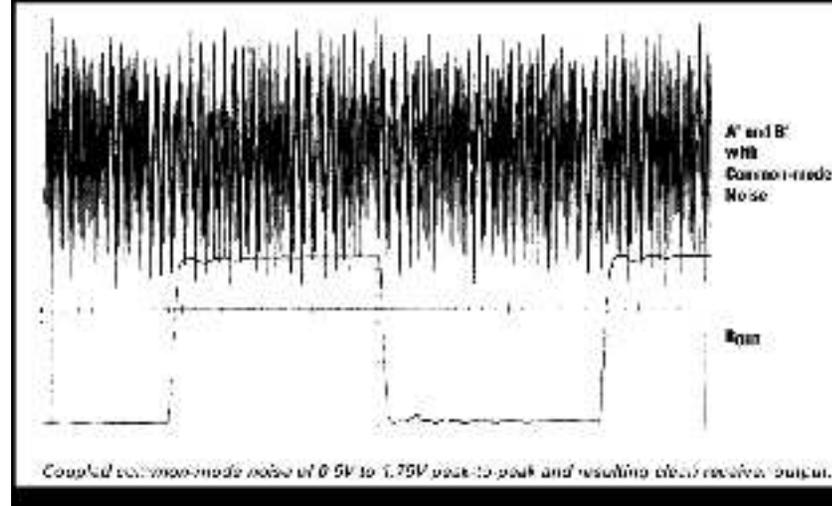
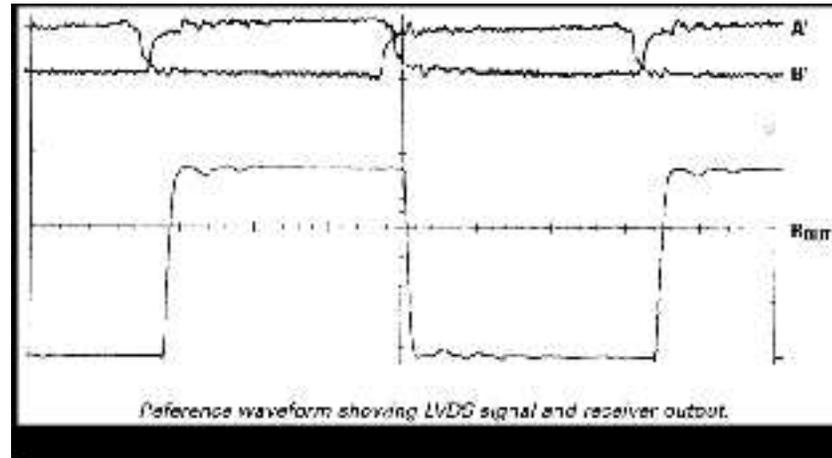


Differential Pair Transmission Line



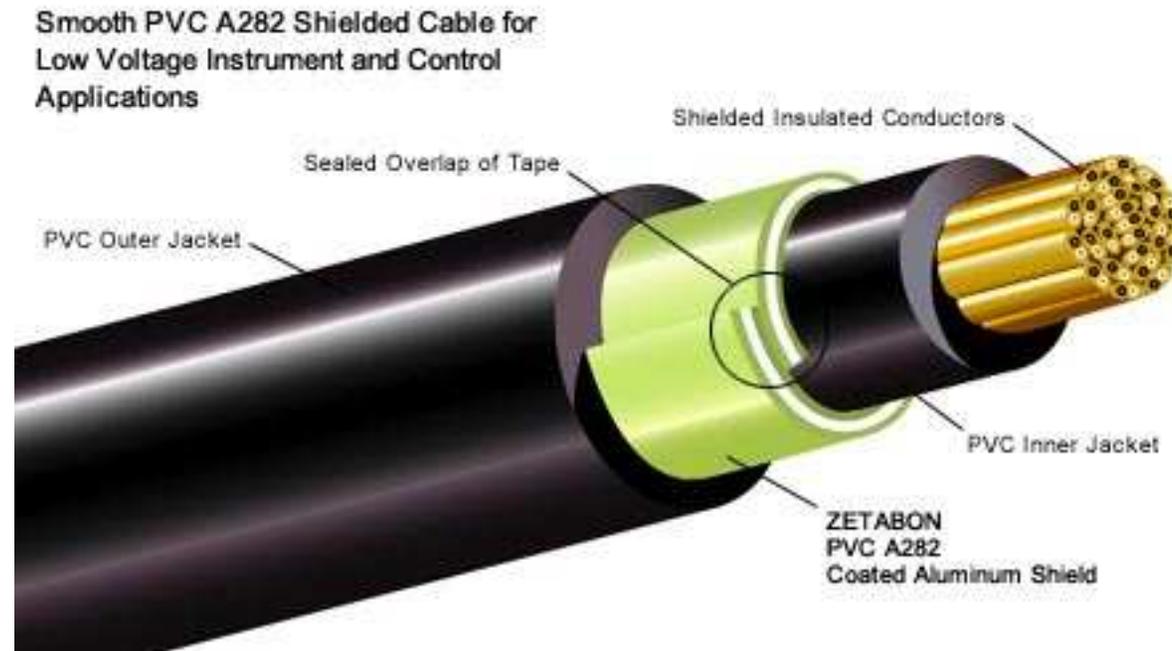
What Are Some Solutions?

(differential signaling works quite well)

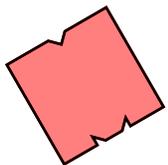


What Are Some Solutions?

Another type of shielding:



**Couples extremely well with previous sol'n
(less effective if used for single-ended
transmission)**



What Are Some Solutions?

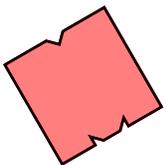
IN GENERAL:

Prevent the Problem

- Requires no change in design practice; no learning curve, no increase in NRE design costs
- The mechanism might be expensive or skittish, or both

Design Around the Problem

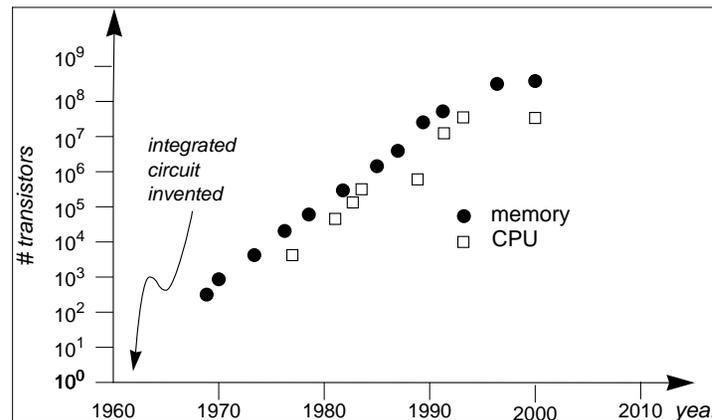
- Requires engineering creativity, willingness to be unconventional
- First attempt might not succeed
- Cost/reliability *might* be better (long run)



Historical

Digital design has been an enormously successful paradigm, driven largely by the ability to use CAD tools to verify designs

Result: *exponential increases* in design complexity that were predicted in 1965* and have continued for *FOUR DECADES*

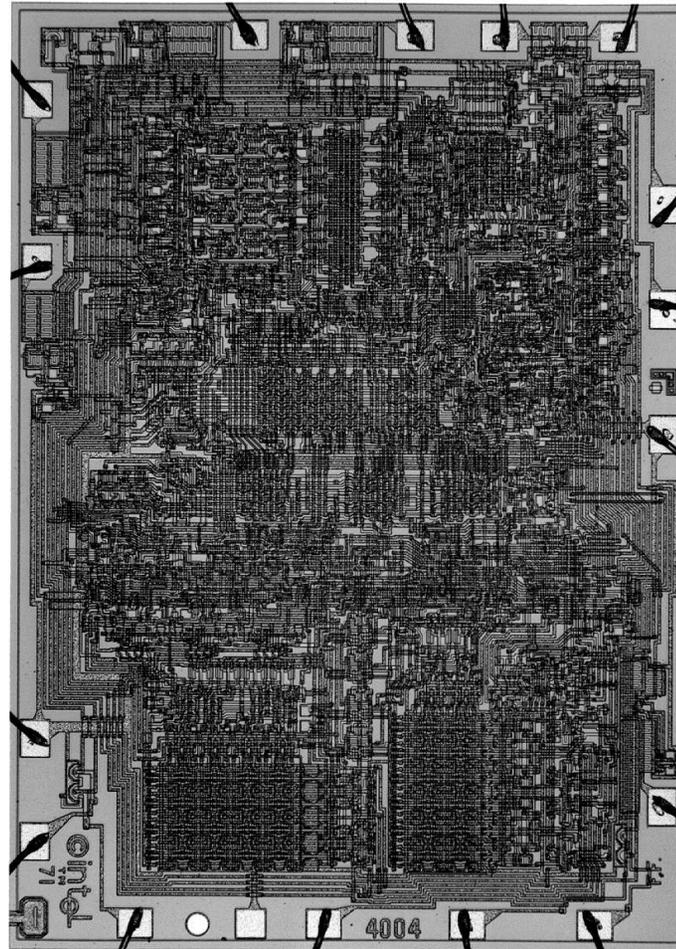


* **Moore's Law.** 1965: transistors on chip doubles every year.
Revised in 1975: number of transistors doubles every two years.

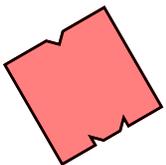


Historical

Intel 4004

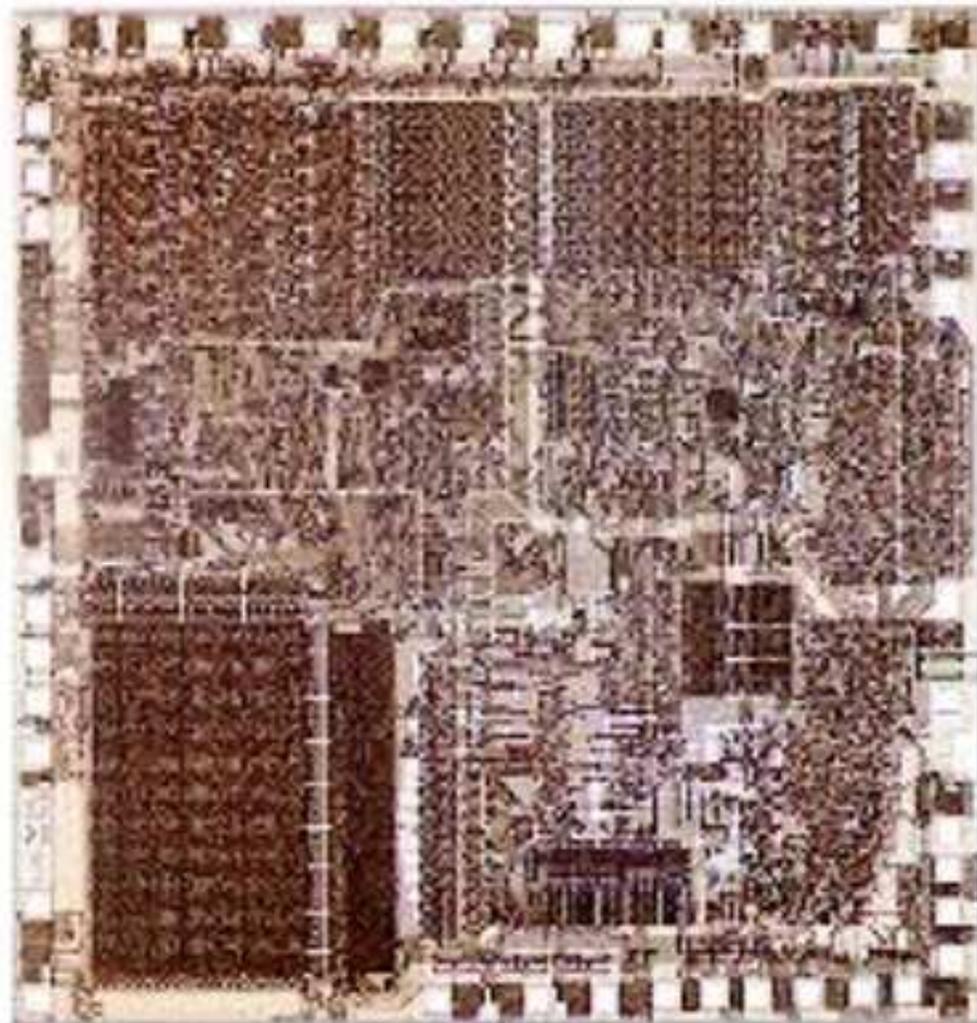


1971
1000 transistors
800 KHz operation

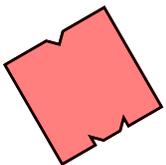


Historical

Intel 8086

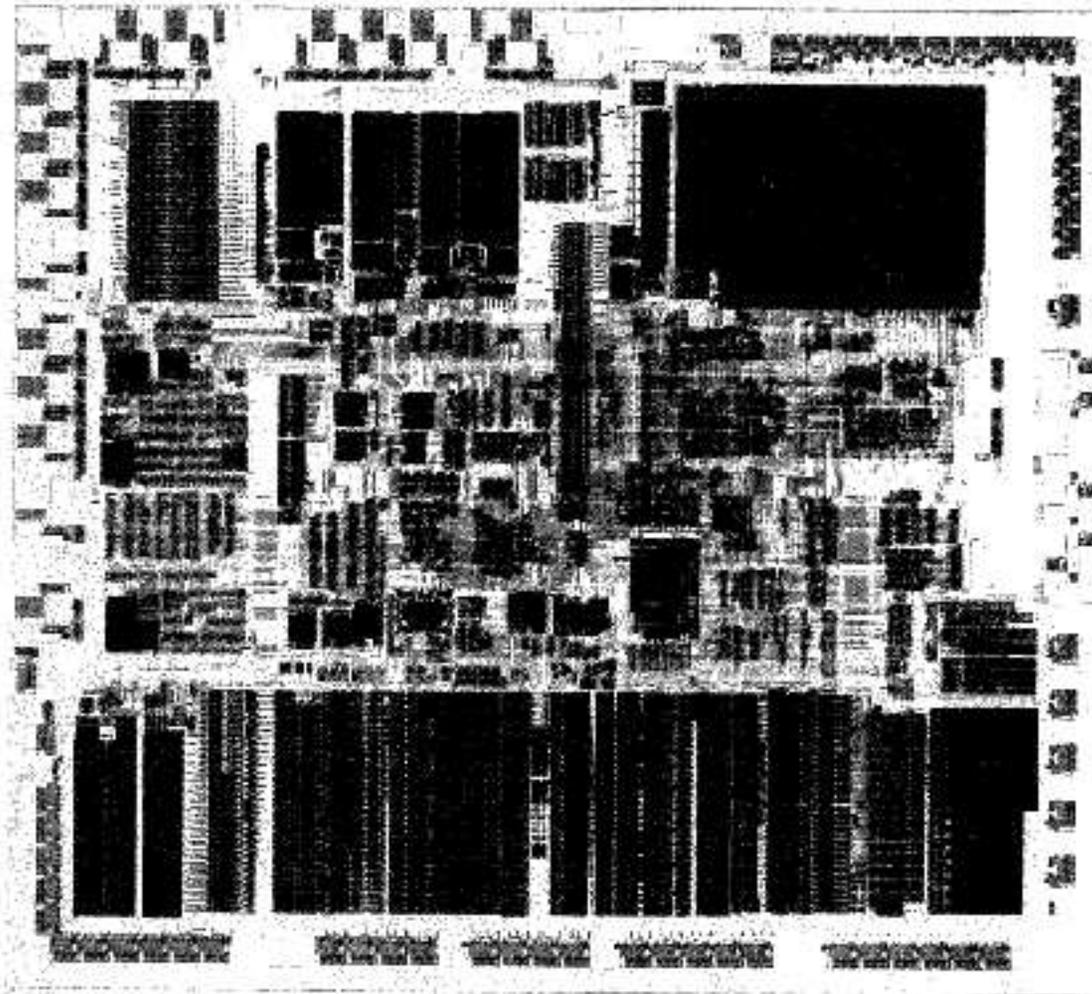


1978
29K trans.
10 MHz

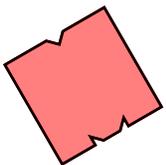


Historical

Intel 80286

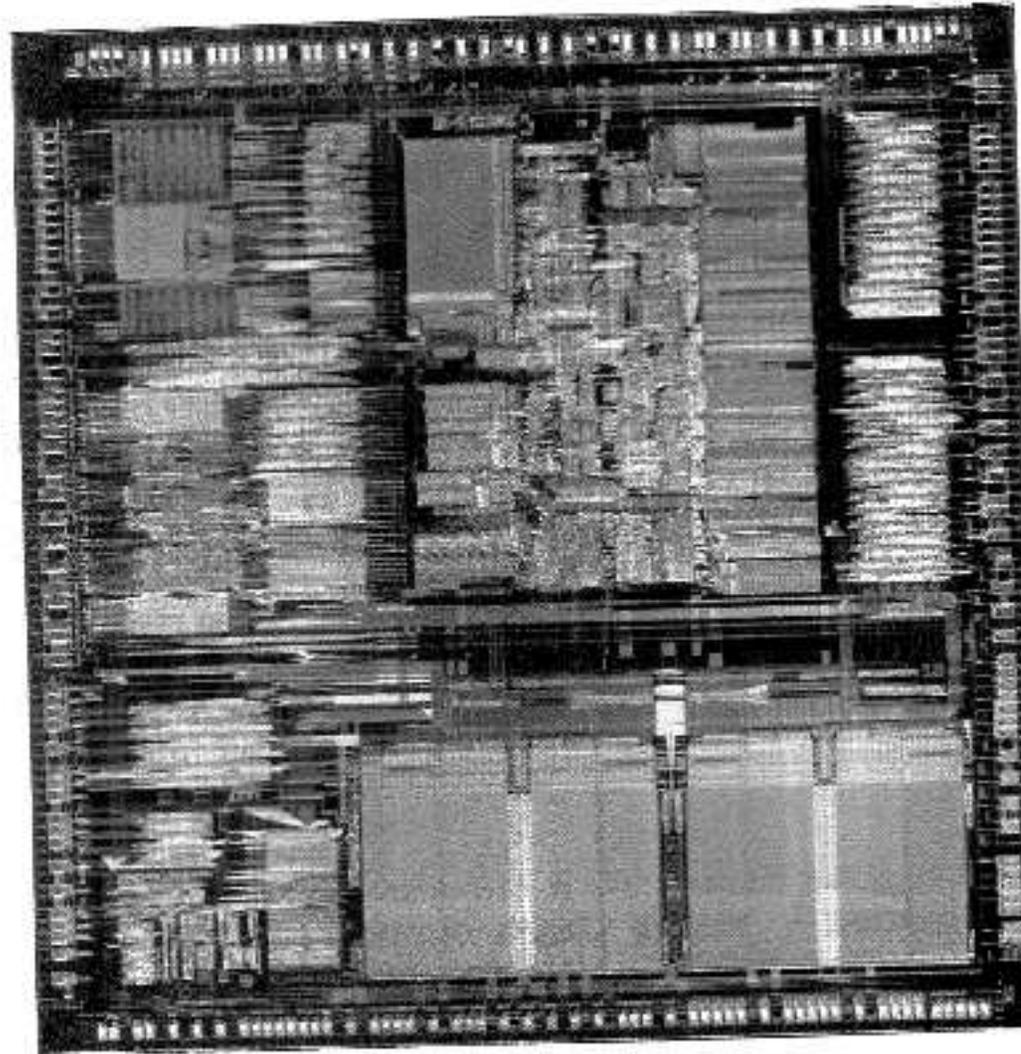


1982
134K trans.
12 MHz



Historical

Intel 80386

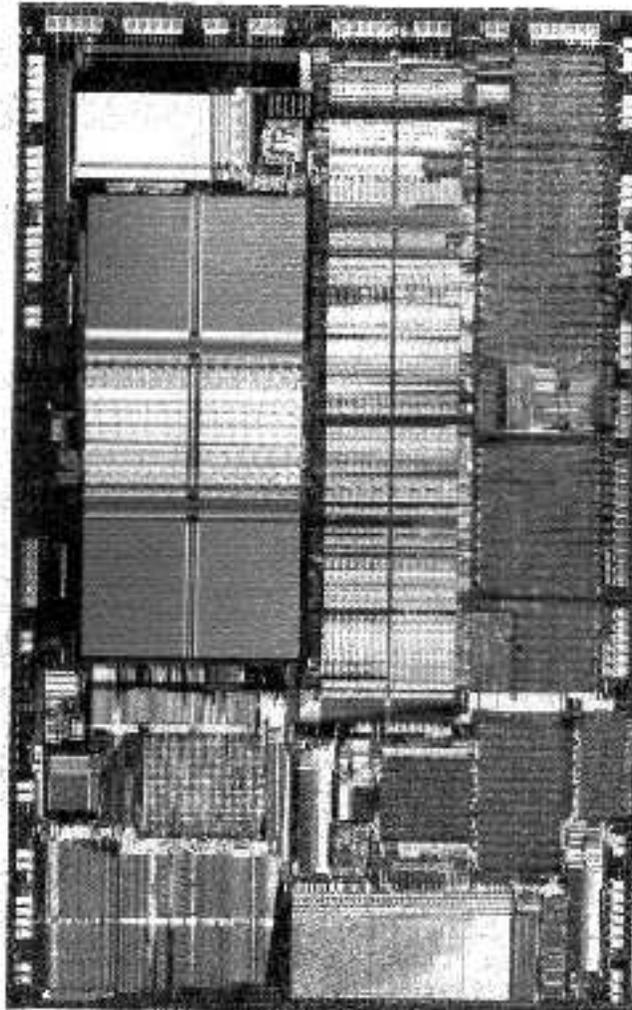


1985/89
275K trans.
16/33 MHz

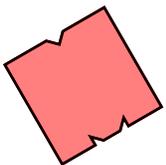


Historical

Intel 80486

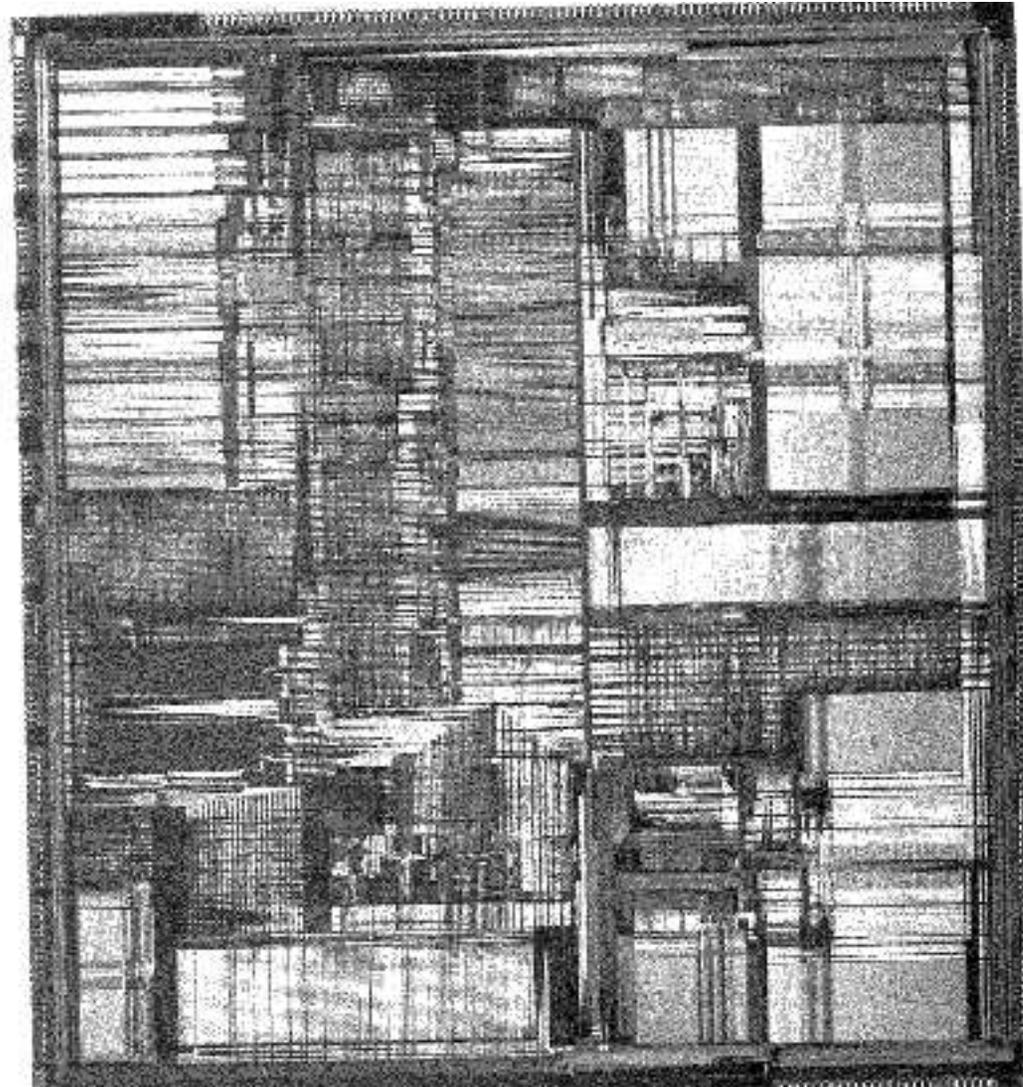


1992
1.6M trans.
100 MHz

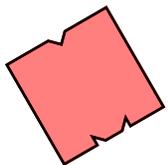


Historical

Intel Pentium



1993/99
3.1/4.5M trans.
60/300 MHz



ENEE 359a
Lecture/s 1+2
Overview

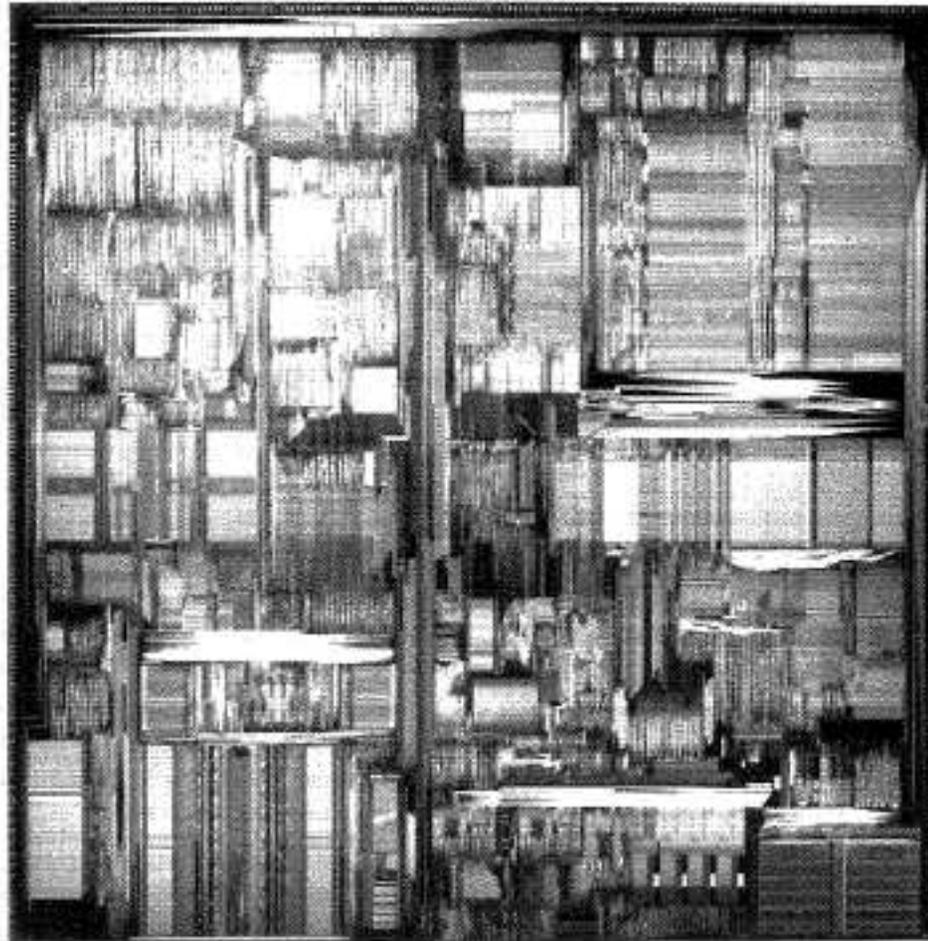
Bruce Jacob

University of
Maryland
ECE Dept.

SLIDE 70

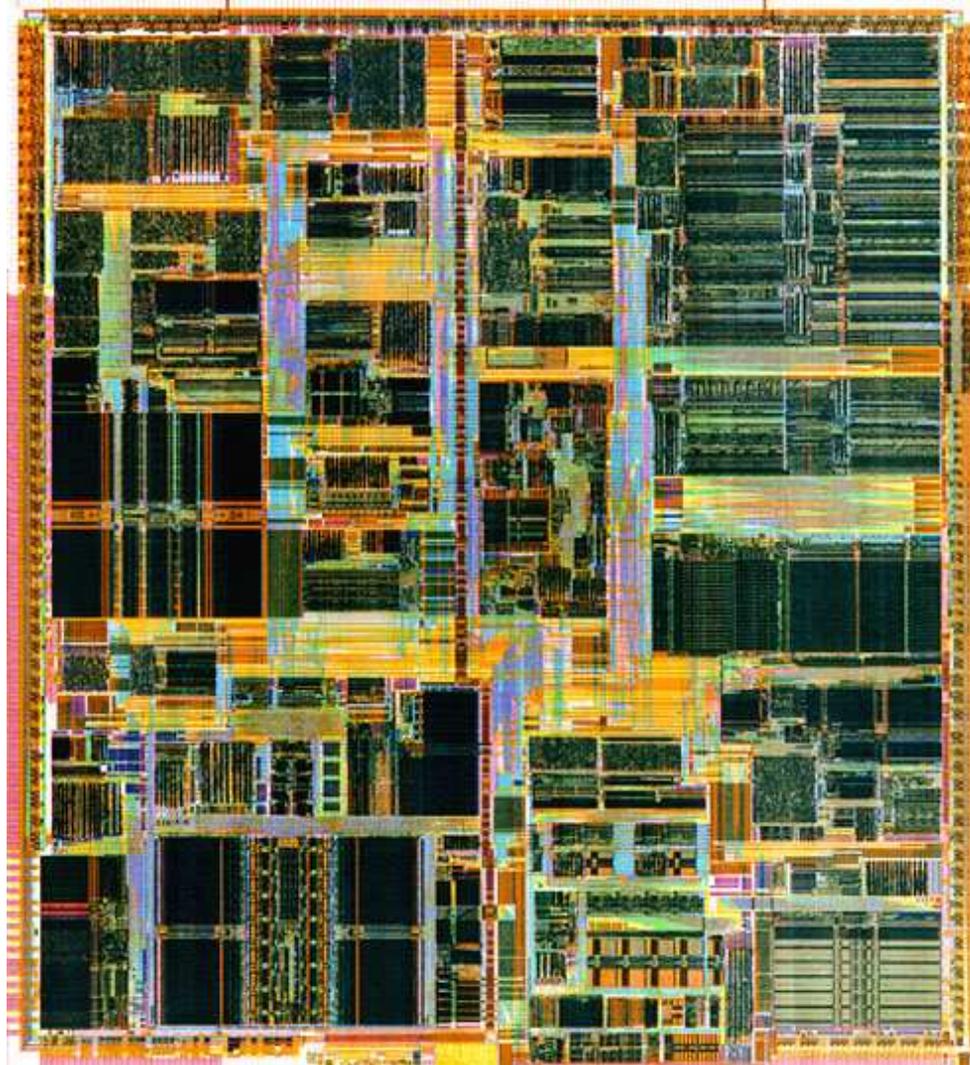
Historical

Intel Pentium Pro

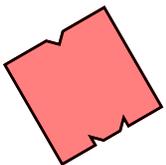


Historical

Intel Pentium IV



2000/04
42/178M trans.
1.4/3.6 GHz



Big Picture

Digital vs. Analog:

- simple vs. complex
- robust vs. fragile

BUT: *This is Only True at Low Speeds*

(And Nothing is Low-Speed Any More)

Analogy of Architect and the Carpenter:

- Architect does a better job if he knows carpentry
- Digital systems design can't be done without using analog concepts

